

DB-G2L-V2 Industrial Development Board hardware manual

Revision History

Draft Date	Revision No.	Description
2023/10/12	V1.0	Initial version.

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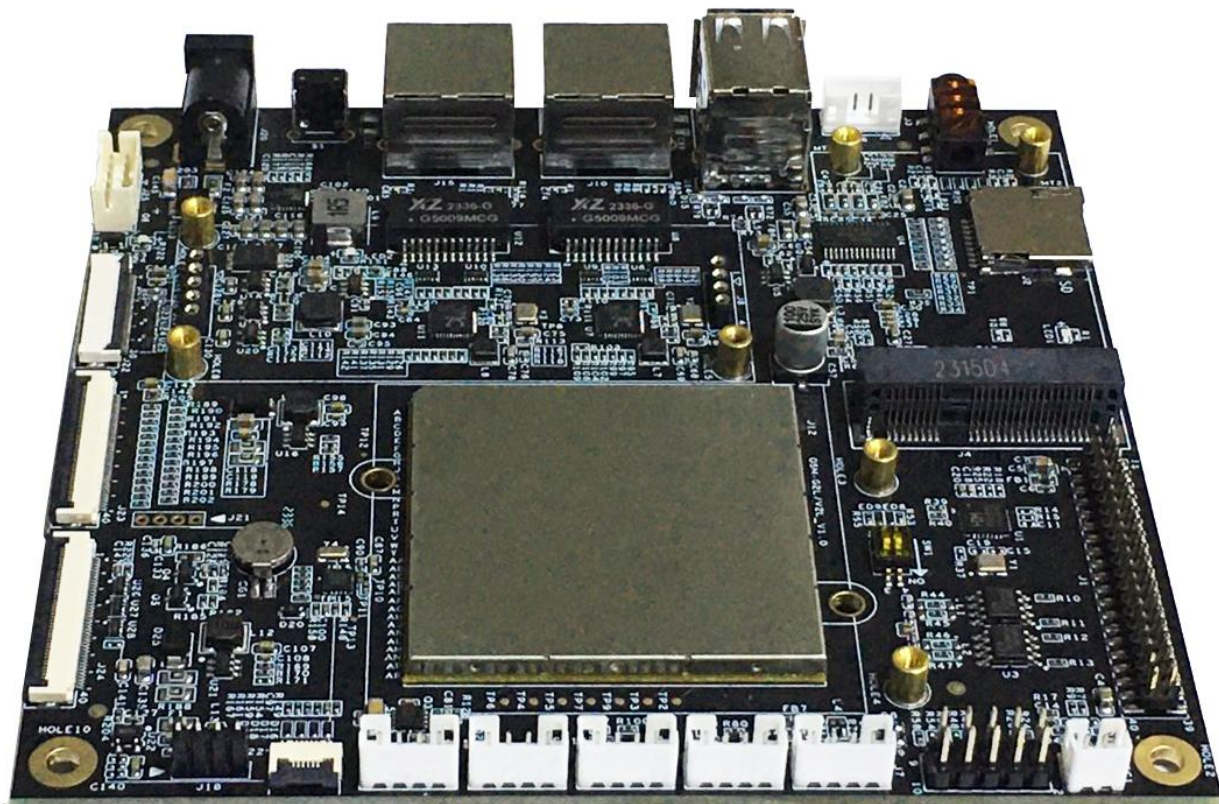
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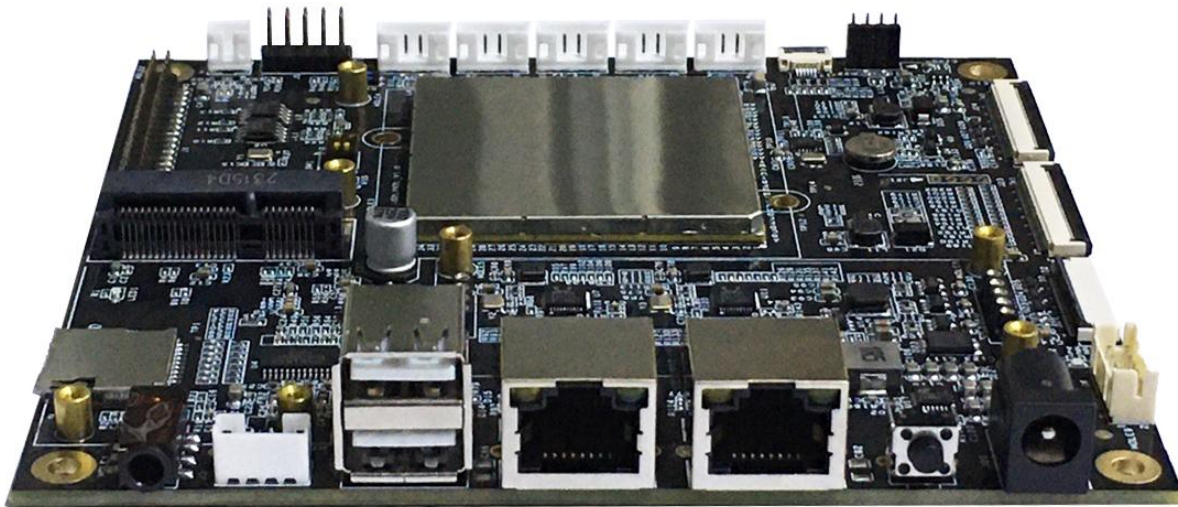
1 Hardware Introduction

DB-G2L-V2 is a high-performance industrial development board based on the industrial-grade Renesas RZ/G2L dual-core ARM Cortex-A55 + single-core ARM Cortex-M33 heterogeneous multicore processor design, consisting of a core board and a backplane. the ARM Cortex-A55 main processing unit clocked at 1.2GHz, integrates the latest high-performance ARM Cortex-A55 main processing unit with 1.2GHz, integrated with the latest high-performance CPU and GPU, and also adopts a security island with Cortex-R5 dual-core lock-step mode, which can be applied to scenarios with stringent requirements on security performance.

The development board is rich in interface resources, leading to a dual-channel network port, 2x CAN-bus, 3x USB2.0, multiple serial ports, on-board USB WiFi module, support for 4G module, while leading to MIPI LCD, CAMERA, RGB LCD, LINE IN, LINE OUT, MIC IN and other audio and video multimedia interfaces, so that the user can quickly carry out the evaluation of product solutions and technology pre-research. and technology pre-study.



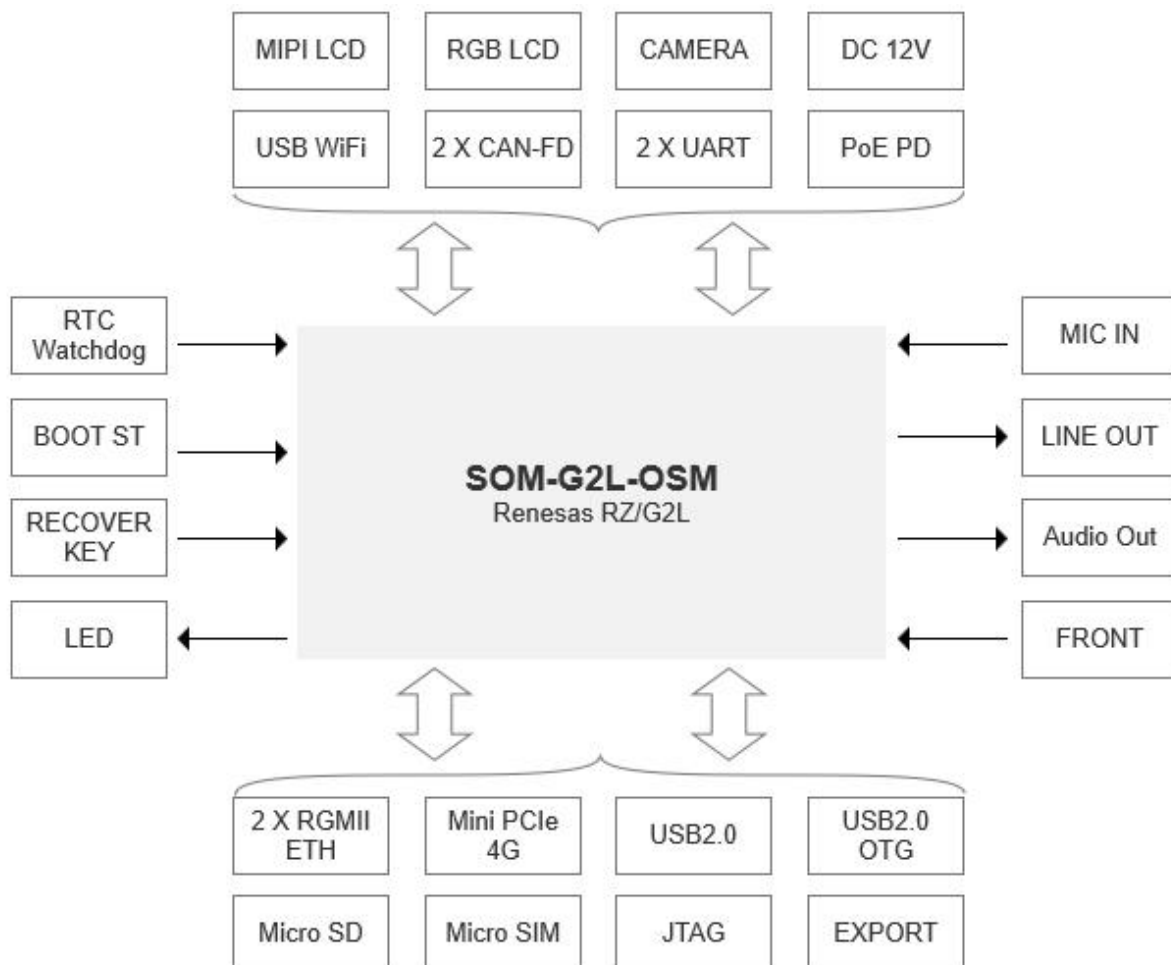
Development board front view



Development board side view

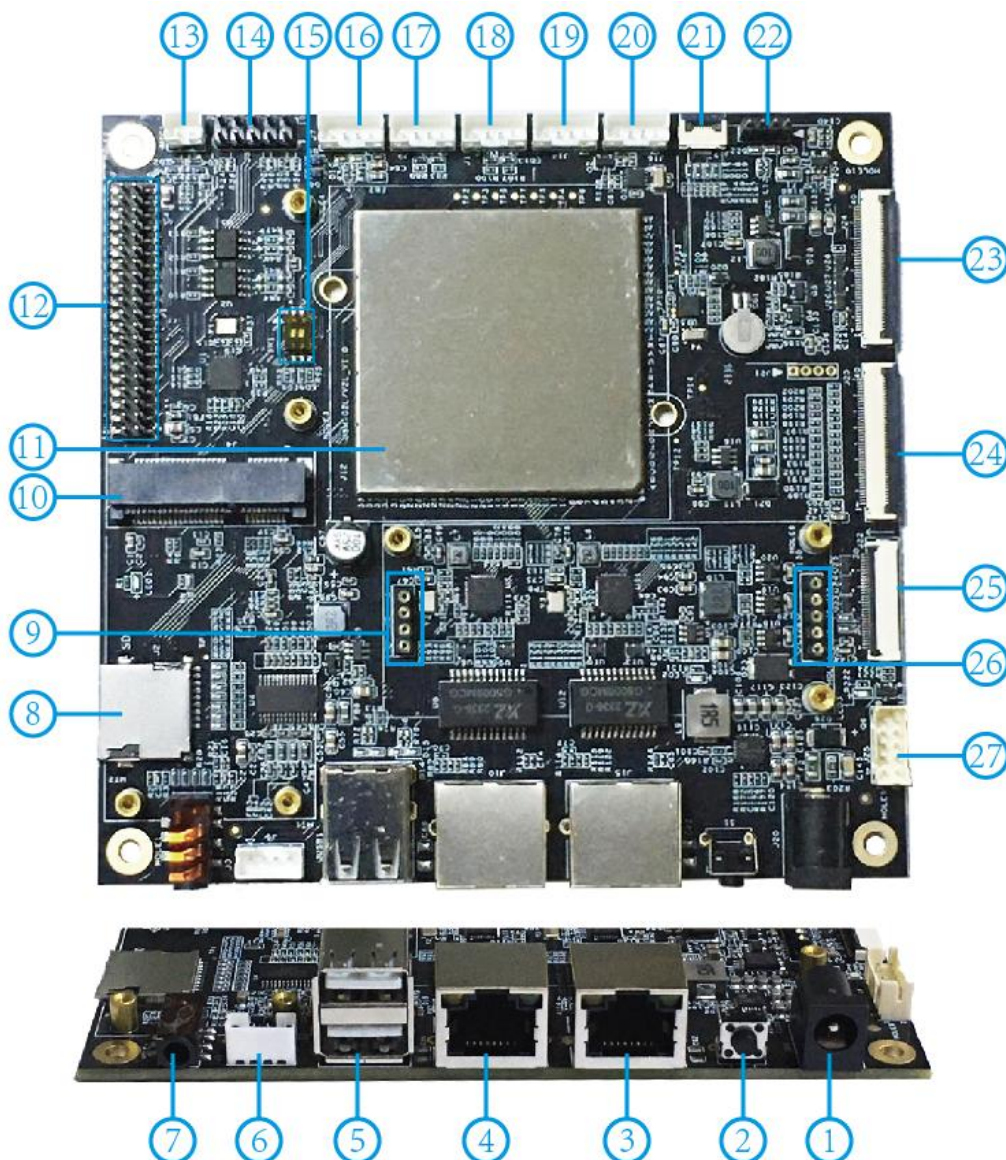
2 Software And Hardware Parameters

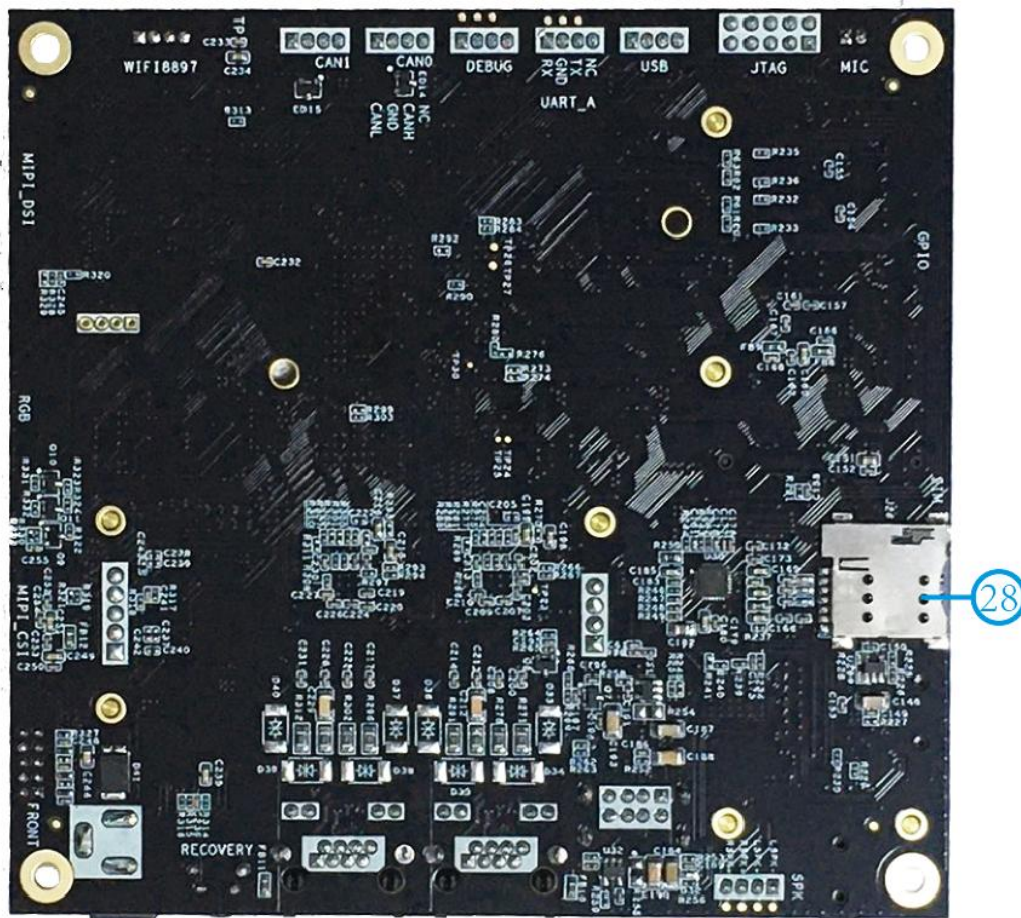
2.1 Hardware Block Diagram



Development board hardware block diagram

2.2 Development Board Interface Definitions





Development board interface definition diagram

No.	Label	Functional Description	Remark
1	J20	DC Power Interface	1x 12V input power connector for 5.5mm OD, 2.1mm ID power plugs
2	S1	RECOVER Key	Access to the system burn-in button
3	J15	Ethernet-2	RJ45 ethernet-2 interface
4	J10	Ethernet-1	RJ45 ethernet-1 interface (PoE PD support, optional)
5	JUSB1	USB2.0	1x USB2.0 HOST(USB2 HUB) Type A lower level 1x USB2.0 OTG Type A upper level Remarks:After the USB_B bus i s expanded with four signals through the USB2.0 HUB, one of the signals is led out directly. USB_A bus direct lead
6	J6	SPK	1x 4PinWhite Terminal Block, 2.0mm Spacing
7	J3	Audio	1x LINE OUT+MIC IN connector, 3.5mm audio cradle
8	J2	Micro SD	1x Micro SD card slot

9	J8	PoE PD Input	1x 4Pin Black Row Holder, 2.0mm Spacing
10	J4	4G	1x Mini PCIe connected via USB2.0 HUB
11	J13	SOM-G2L-OSM Core boards	1x 662Pin LGA
12	J1	EXPORT	1x EXPORT Expansion Connector, 2x20pin Pin Header, 2.0mm Pitch
13	MIC1	MIC	1x 2Pin white terminal block, 2.0mm spacing
14	J5	JTAG	2x 5Pin header , 2.54mm spacing
15	SW1	BOOT SET	1x 2bit boot mode selection dip switch
16	J7	USB2.0 touch screen interface	1x 4Pin white terminal block, 2.0mm spacing
17	J9	UART	1x 4Pin white terminal block, 2.0mm spacing
18	J11	Debut	1x 4Pin white terminal block, 2.0mm spacing
19	J14	CAN-FD-1	1x 4Pin white terminal block, 2.0mm spacing
20	J16	CAN-FD-2	1x 4Pin white terminal block, 2.0mm spacing
21	J17	Capacitive Touch Screen Interface	1x 6Pin FFC connector, 0.5mm spacing
22	J18	USB WiFi	1x 4Pin Pin Array, 2.0mm Spacing Connects via USB2.0 HOST
23	J24	MIPI LCD interface	1x 40Pin FFC Connector, 0.5mm Spacing
24	J23	RGB LCD interface	1x 40Pin FFC Connector, 0.5mm Spacing
25	J22	CAMERA	1x 30Pin FFC Connector, 0.5mm Spacing
26	J19	PoE PD Output	1x 5Pin Black Row Holder, 2.0mm Spacing
27	J25	FRONT	2x5pin header, 2.0mm spacing
28	J26	Micro SIM	1x 4G Micro SIM card slot

2.3 Hardware Parameters

CPU	Renesas RZ/G2L
	2x ARM Cortex-A55, 1.2GHz main frequency, support floating point function
	ARM Cortex-M33,dedicated real-time processing unit at 200MHz
	VPU: Encoding / Decoding support H.264 / AVC (High Profile / Main Profile / Baseline Profile), H.264 / MVC (Stereo High Profile), maximum pixel rate: 1920 x 1080 x 30 fps
	GPU: Mali-G31 500MHz, support OpenGL ES 1.1/2.0/3.1/3.2、Vulkan 1.1、OpenCL 2.0

	ISU: Maximum input image resolution: 5M (2800×2047), Maximum output image resolution: Full HD (1920×1080), support color format conversion: RGB / ARGB / YcbCr422 / YcbCr420 / RAW(Grayscale)
ROM	16/32GB eMMC 128Mb SPI FLASH
RAM	2GB DDR4

2.4 Peripheral Configuration

The main peripheral configurations and performance parameters are shown in the following table.

Peripheral Interface	Quantities	Performance Parameters
MIPI CSI	1	1x CAMERA, 30pin FFC connector, 0.5mm spacing
MIPI DSI	1	1x MIPI LCD, 40pin (display) FCC connector + 6pin (capacitive touch screen) FFC connector, 0.5mm spacing, Maximum resolution support up to 1920 x 1080@60fps
DVP	1	1x 40Pin FFC connector with 0.5mm spacing, supports WXGA (1280 × 800) 60fps
USB HOST	1	USB 2.0 Type A (supports up to 480 Mbps)
USB OTG	1	USB 2.0 Type A (supports up to 480 Mbps)
WiFi	1	USB WiFi, 4pin Black Terminal Block, 2.0mm Pitch Note: After the USB_B bus expands four signals through the USB2.0 HUB, one of the expansion signals The signal is then expanded through the USB2.0 HUB.
Ethernet	2	2x RJ45 interfaces, RMII/RGMII support, 10/100/1000Mbps network adaptive; The first Ethernet supports PoE PD.
4G	1	Mini PCIe interface via USB2.0 HUB
Micro SD	1	Micro SD card slot
CAN FD	2	2x 4 pin white terminal blocks, 2.0mm spacing
SPK	1	4 pin white terminal blocks, 2.0mm spacing
LINE OUT+MIC IN	1	3.5mm Audio holder
MIC	1	2 pin white terminal blocks, 2.0mm spacing
JTAG	1	Supports JTAG debugging interface
RTC	1	Suitable for button cell MS621 (3V rechargeable)

Watchdog	1	1x Watchdog		
Debug	1	Debug UART white terminal blocks, 2.0mm spacing		
UART	1	UART 4 pin white terminal blocks, 2.0mm spacing		
I2C	1	6pin FFC connector with 0.5mm pitch		
BOOT SET	1	2bit startup mode selection dip switch		
POWER	1	12V DC input power connector for 5.5mm OD, 2.1mm ID power plugs		
EXPORT	1	SPI	2	2x 20Pin black pins, 2.0mm spacing
		UART	4	
		I2C	1	
		GPIO	5	
		5V	1	
		3.3V	1	

2.5 Software Parameters

Kernel	4.19	
Uboot	2020.10	
OS	Yocto	
Driver support	eMMC	DDR4
	MMC/SD	LED
	KEY	USB WIFI/4G/Mouse
	UART	I2C
	CAN-FD	MIPI CAMERA
	MIPI LCD	Ethernet
	LINE IN/OUT	Touch Screen
	RTC	

2.6 Development Information

- Provide core board pin definition, core board 3D graphic files, editable base board schematic, editable base board PCB, chip Data sheet, shorten the hardware design cycle.
- Provides file system images, kernel driver source code, and a wealth of demo programs
- Provides complete platform development kits, getting started tutorials to save time on software organization and make application development easier.

3 Electrical Characteristics

3.1 Operating Environment

Environmental Parameters	Minimum	Typical	Maximum
Operating temperature	-40°C	/	85°C
Storage temperature	-50°C	/	90°C
Operating humidity	35% (no condensation)	/	75% (no condensation)
Storage humidity	35% (no condensation)	/	75% (no condensation)
Operating voltage	9V	12.0V	18V

3.2 GPIO DC Characterization

Parameters	Label	Specifications				Remark
		Minimum	Typical	Maximum	Unit	
High level input voltage	VIH	2	--	3.5	V	--
Low level input voltage	VIL	0	--	0.8	V	--
High level output voltage	VOH	2.4	--	--	V	--
Low level output voltage	VOL	--	--	0.2	V	--

Parameters	Label	Specifications				Remark
		Minimum	Typical	Maximum	Unit	

High level input voltage	VIH	0.7xVDD	--	NVCC_3V3	V	--
Low level input voltage	VIL	0	--	0.2xVDD	V	--
High level output voltage	VOH	VDD - 0.2	--	--	V	--
Low level output voltage	VOL	--	--	0.2	V	--

3.3 Power Consumption Parameters

Operating State	Voltage Typical	Current Typical	Power Consumption Typical
Free state	12.0V	0.15A	1.8W
Full load state	12.0V	0.23A	2.76W

Note: Test data is related to specific application scenarios and is for reference only.

Free state: the system is started, the development board is not connected to other external modules, and the program is not executed.

Full load state: the system boots up, the development board is not connected to other external modules, running the DDR pressure read/write test program, the resource utilization of the two ARM Cortex-A53 cores is about 100%.

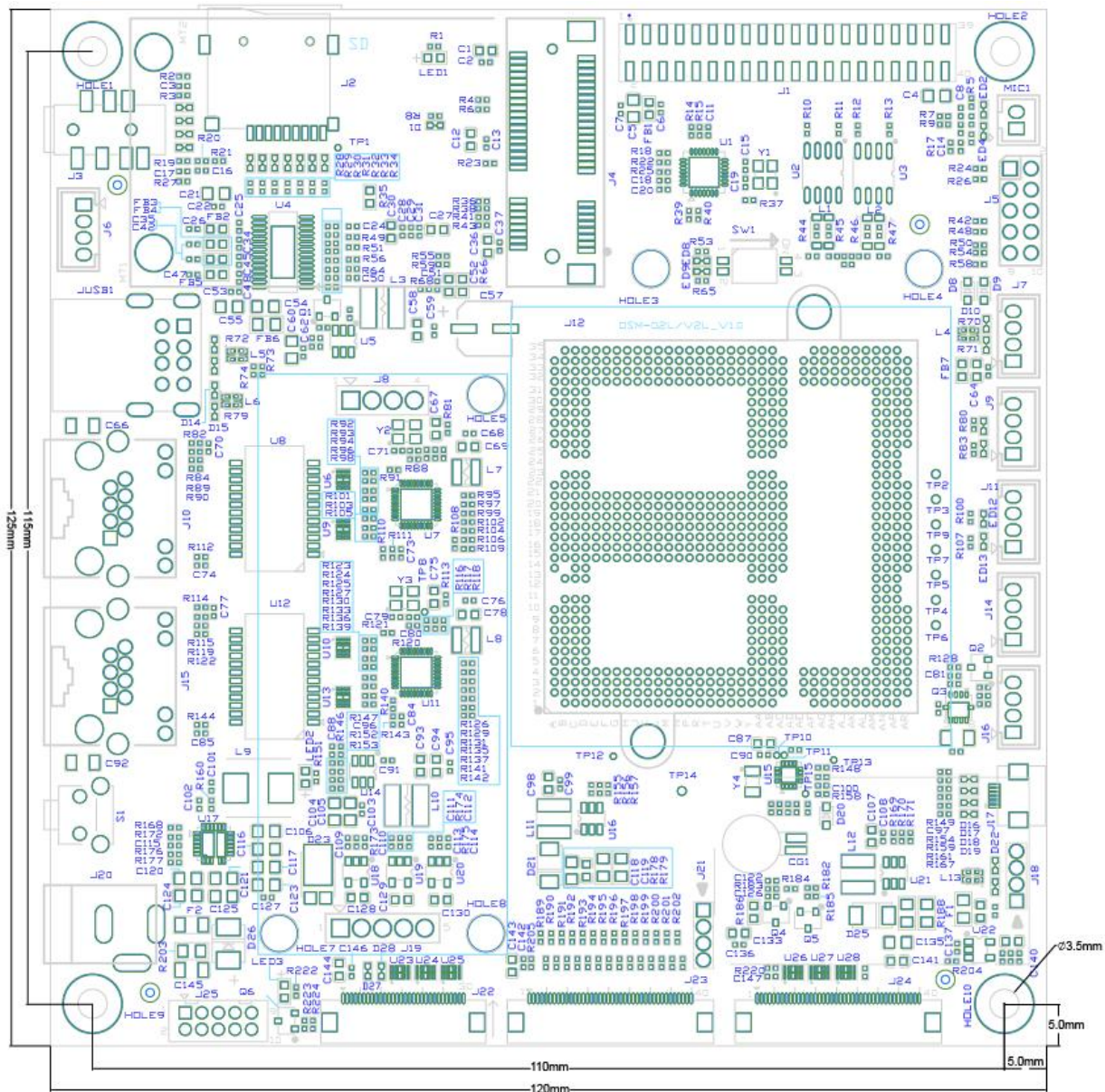
3.4 Interface Speed

Parameters	Specifications				Remark
	Minimum	Typical	Maximum	Unit	
Serial communication speed	--	115200	--	bps	--
SPI communication speed	--	--	52	MHz	--
IIC communication speed	--	100	400	Kbps	--
CAN communication speed	--	--	1	Mbps	--
SD/MMC/SDIO	--	--	104	Mbps	--
USB interface speed	--	--	480	Mbps	--
AD acquisition time	0.7	--	1.25	uS	Fadc=40 MHz

4 Mechanical Dimensions

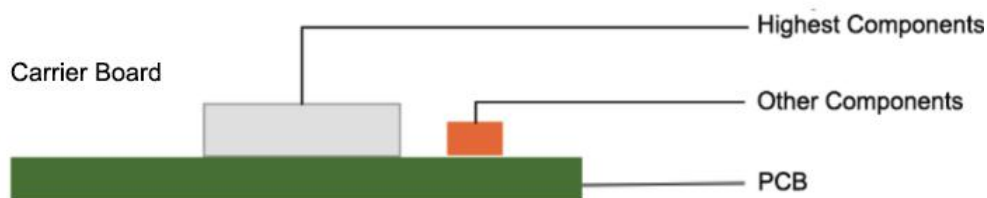
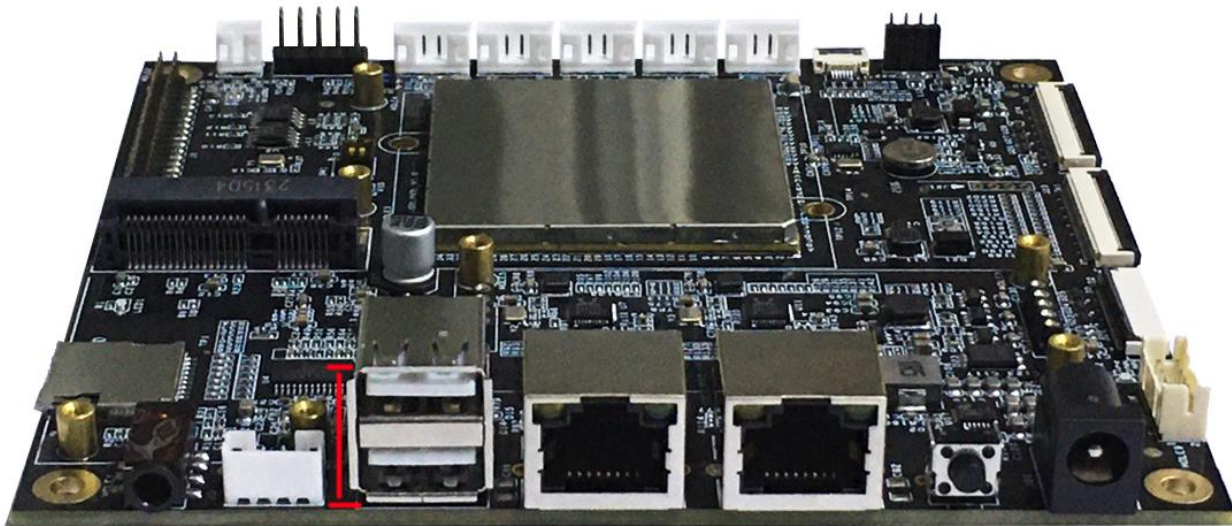
The main hardware-related dimensions of the development board are shown below for reference only.

PCB Size	120mm*125mm
PCB Layers	4 Layers
PCB Board Thickness	1.6mm
Number of mounting holes	4
Maximum component height	22mm
Weights	130g



Development board mechanical dimensions

Maximum component height: the height difference between the highest component level of the development board and the level of the front of the PCB. The highest component on the board is the dual-layer USB sockets(JUSB1).



Schematic of the highest device on the development board

5 Development Board Kit List

5.1 Standard accessories

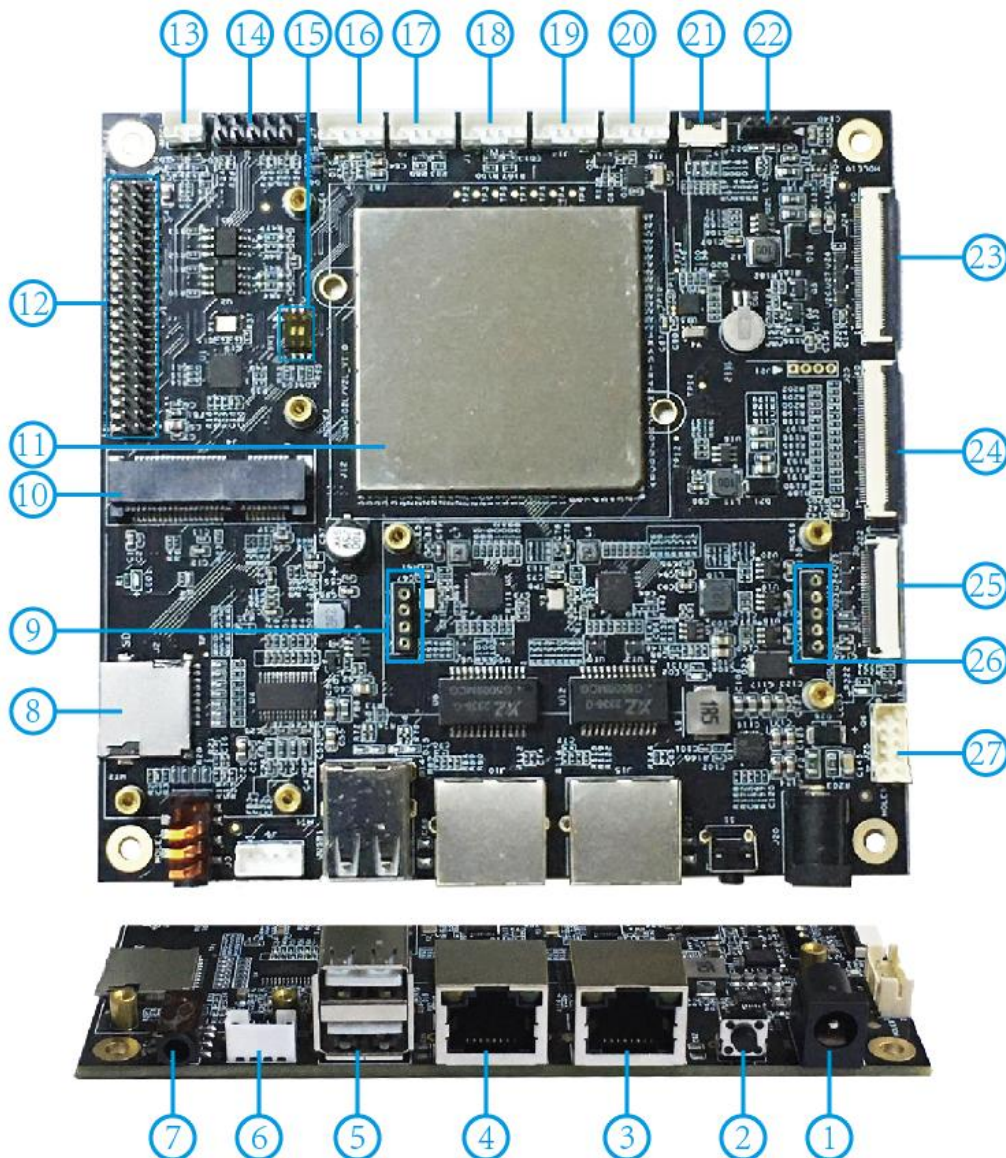
Name	Quantity	Remark
Development Board with Core Board	1	
12V Power Adapter	1	Standard configuration
2.4G Antenna	1	Standard when WiFi function is available

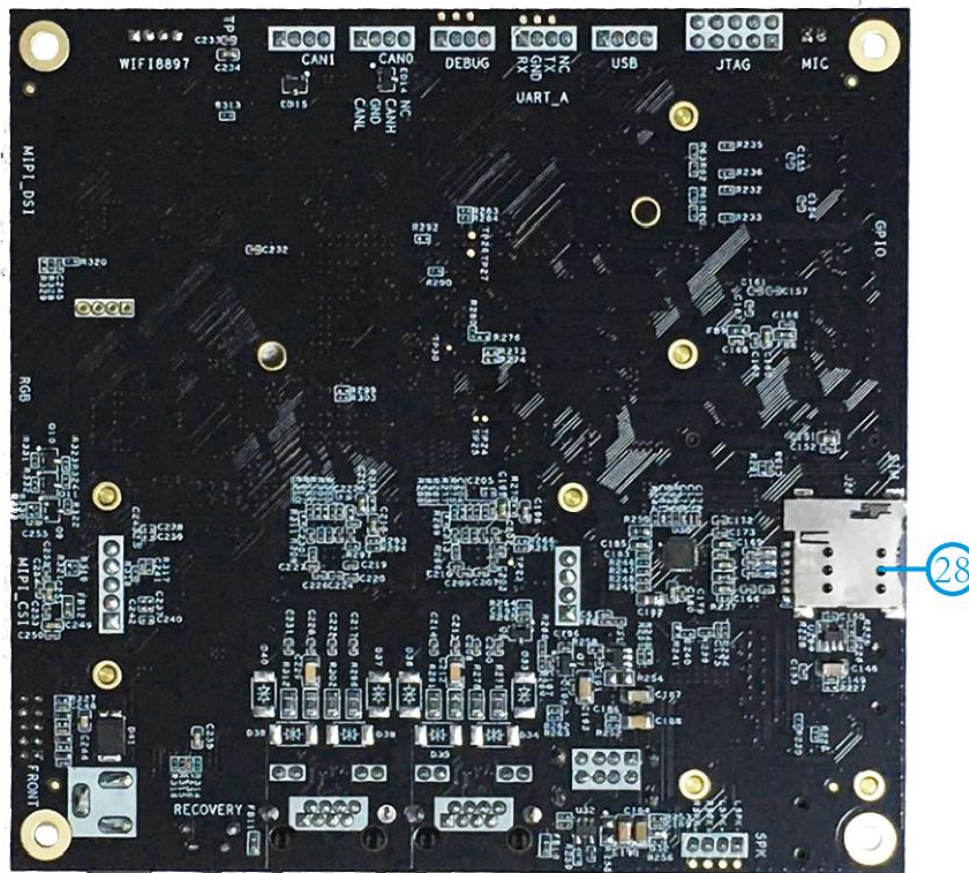
5.2 Optional Accessories

Name	Model	Quantity	Remark
Serial Debugging Tools		1	

10.1" MIPI LCD with Capacitive Touch	WD101HKM40AB-E6-05/HK101TLEDM-KM01	1	1280x800
7" MIPI LCD with Capacitive Touch	AML070JGI50-07403L-A	1	1024x600
4.3" RGB LCD with Capacitive Touch	AVD-TT43WQ-CW-234-A SP	1	480x272
4.3" RGB LCD with Capacitive Touch	HX043JGI50-43103	1	800x480
PoE PD Module	POE-12V	1	
MIPI CSI Camera	ZH13850-ZH-001	1	
4G Module	EC25	1	Mini PCIe interface
WiFi Module	88W8897	1	USB2.0 interface

6 Development Board Interface Definitions





Development Board interface definition diagram

No.	Label	Functional Description	Remark
1	J20	DC Power Interface	1x 12V input power connector for 5.5mm OD, 2.1mm ID power plugs
2	S1	RECOVER Key	Access to the system burn-in button
3	J15	Ethernet-2	RJ45 ethernet-2 interface
4	J10	Ethernet-1	RJ45 ethernet-1 interface (PoE PD support, optional)
5	JUSB1	USB2.0	1x USB2.0 HOST(USB2 HUB) Type A lower level 1x USB2.0 OTG Type A upper level Remarks:After the USB_B bus i s expanded with four signals through the USB2.0 HUB, one of the signals is led out directly. USB_A bus direct lead
6	J6	SPK	1x 4PinWhite Terminal Block, 2.0mm Spacing
7	J3	Audio	1x LINE OUT+MIC IN connector, 3.5mm audio cradle
8	J2	Micro SD	1x Micro SD card slot

9	J8	PoE PD Input	1x 4Pin Black Row Holder, 2.0mm Spacing
10	J4	4G	1x Mini PCIe connected via USB2.0 HUB
11	J13	SOM-G2L-OSM Core boards	1x 662Pin LGA
12	J1	EXPORT	1x EXPORT Expansion Connector, 2x20pin Pin Header, 2.0mm Pitch
13	MIC1	MIC	1x 2Pin white terminal block, 2.0mm spacing
14	J5	JTAG	2x 5Pin header, 2.54mm spacing
15	SW1	BOOT SET	1x 2bit boot mode selection dip switch
16	J7	USB2.0 touch screen interface	1x 4Pin white terminal block, 2.0mm spacing
17	J9	UART	1x 4Pin white terminal block, 2.0mm spacing
18	J11	Debut	1x 4Pin white terminal block, 2.0mm spacing
19	J14	CAN-FD-1	1x 4Pin white terminal block, 2.0mm spacing
20	J16	CAN-FD-2	1x 4Pin white terminal block, 2.0mm spacing
21	J17	Capacitive Touch Screen Interface	1x 6Pin FFC connector, 0.5mm spacing
22	J18	USB WiFi	1x 4Pin Pin Array, 2.0mm Spacing Connects via USB2.0 HOST
23	J24	MIPI LCD interface	1x 40Pin FFC Connector, 0.5mm Spacing
24	J23	RGB LCD interface	1x 40Pin FFC Connector, 0.5mm Spacing
25	J22	CAMERA	1x 30Pin FFC Connector, 0.5mm Spacing
26	J19	PoE PD Output	1x 5Pin Black Row Holder, 2.0mm Spacing
27	J25	FRONT	2x5pin header, 2.0mm spacing
28	J26	Micro SIM	1x 4G Micro SIM card slot



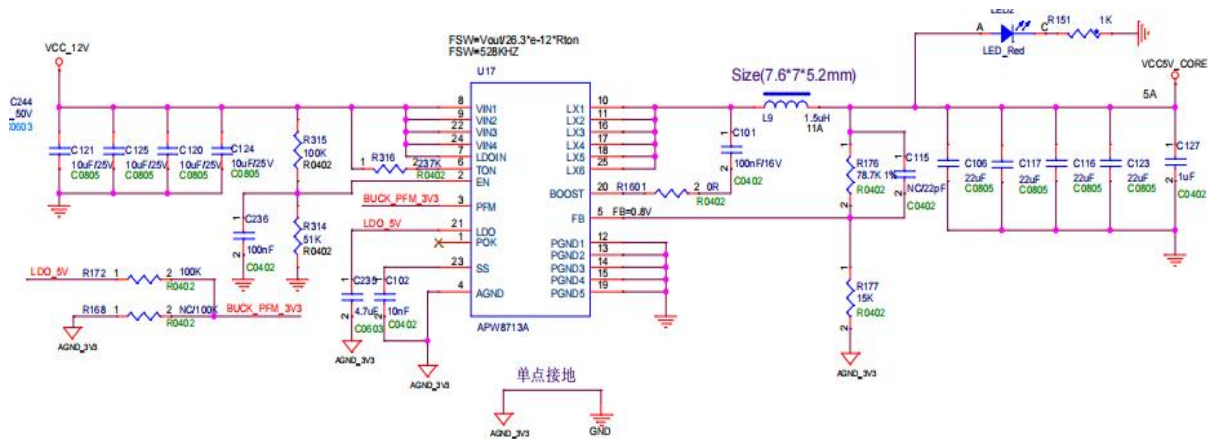
It is recommended to use a 12V 2A DC power adapter as the power input. For non-12V DC power adapters, please refer to Power Consumption and Power Supply Requirements to select the appropriate power supply.



Label	Pin	Functional Description	Signal description	Remark
J20	1	System power supply input +	12V	DC Socket ,DC connector
	2	Power ground	GND	Outer diameter 5.5mm, inner
	3	Power ground	GND	diameter 2.1mm

6.1.2 Primary conversion circuit

The VIN to 5V recommended circuit is shown in the figure.



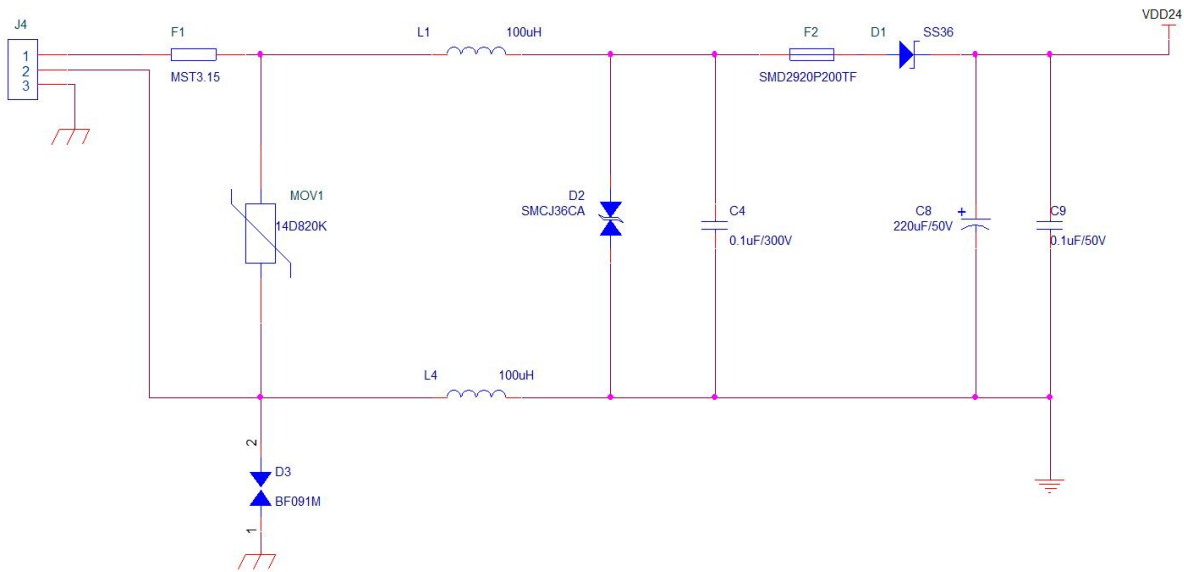
VIN to 5V Recommended Circuit

When the voltage difference between the input and output power supplies is large and the load current is high, the power conversion chip needs to use a DC-DC device with high conversion efficiency, instead of an LDO device, which will burn out the device due to high heat generation.

The reference circuit uses the APW8713A device, which has an input voltage range of 2.7~28V, a maximum output current of 8A, a conversion efficiency of up to 95%, an inductance selectable from 1~4.7uH, and a current rating greater than the load current.

Power Protection Circuit

When the environment in which the equipment is located is harsh, such as when it is placed outdoors and may be subjected to lightning strikes, it is necessary to protect the power supply section. The recommended protection circuit is shown in the figure.



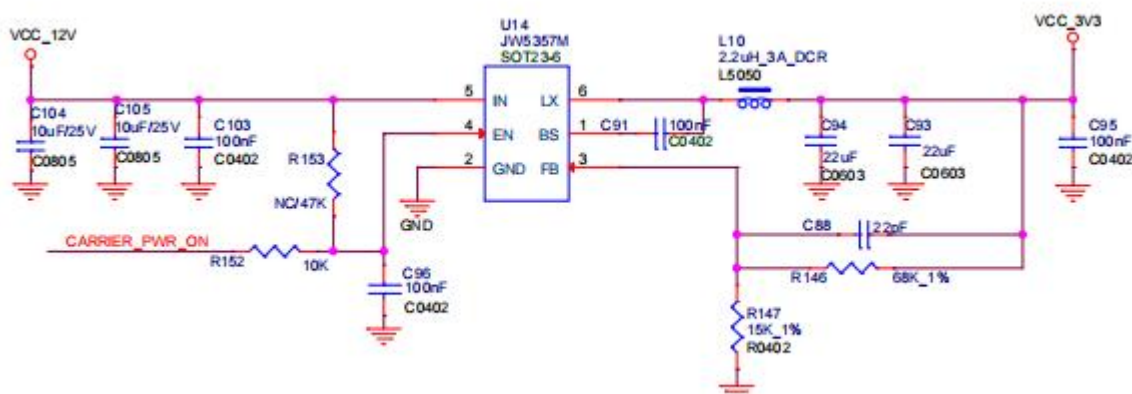
Power supply protection circuit

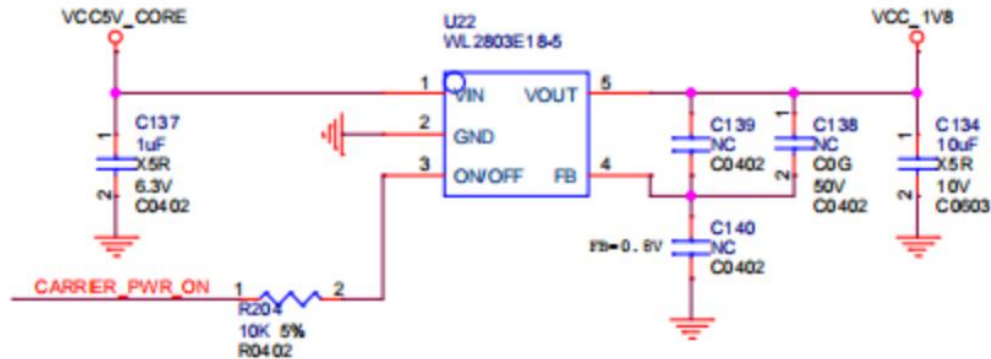
When surge voltage or current occurs in the power port, varistor MOV1 and gas discharge tube D3 form the first level of protection to absorb larger surges. d2 is a TVS tube, mainly for the absorption of residual voltage after the first level of protection. Since the response time of TVS is faster than that of gas discharge tube, in order to prevent TVS from being burnt before the response of gas discharge tube, it is necessary to connect an inductor in series between the two protection circuits to play the effect of time delay.

D1 is a Schottky diode to realize the anti-reverse function.

6.1.3 Secondary conversion circuit

Development board other power supply, such as 3.3V, 1.8V, etc., can be obtained by 12V\5V again step-down, the recommended circuit shown in Figure.





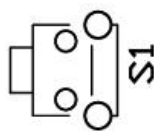
5V to 3.3V circuit

JW5357M is a two-way power conversion device with a maximum output current of 3A and an adjustable output voltage, and the EN pin is connected to the core board. CARRIER_PWR_ON (V17) on , realizing the timing requirement that the core board is powered up before the base board.

Users can choose other models of power supply devices according to actual needs.

6.2 RECOVERY Key(S1)

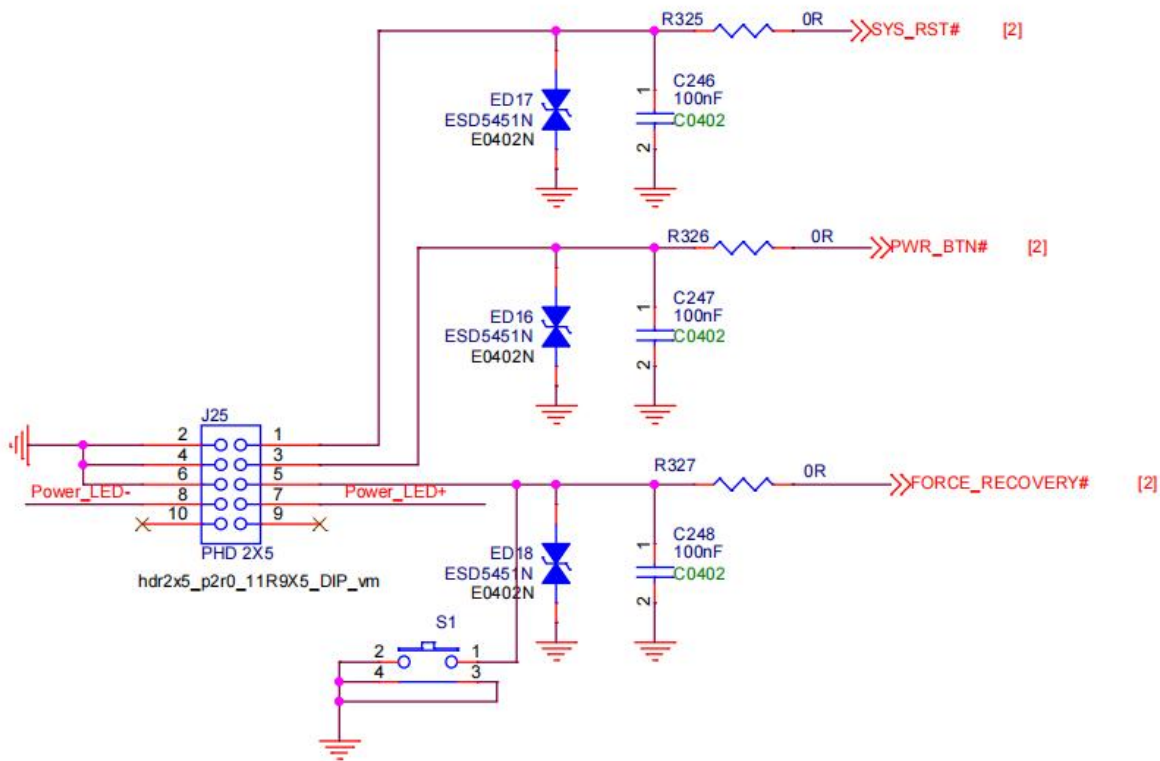
The development board has designed a RECOVERY key for system burning.



Recovery key diagram

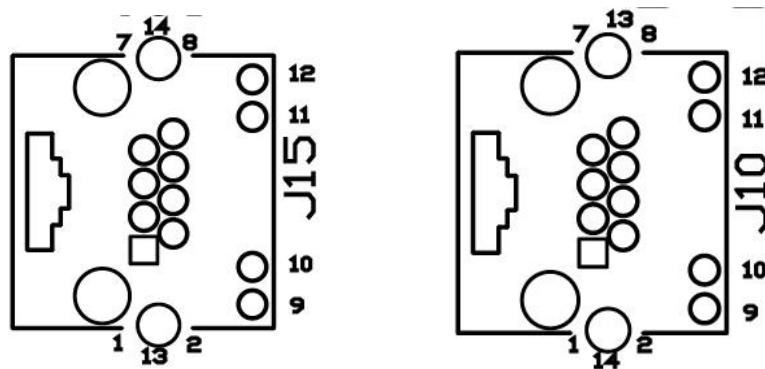
6.2.1 Pin Definitions

Label	Pin	Functional Description	Signal description	Remark
S1	1	Burn mode	RECOVERY	Press the button to enter burn mode



6.3 Ethernet Interface (J15, J10)

Designed with 2 x 1000M Ethernet interface using RJ45 connectors



Ethernet interface schematic

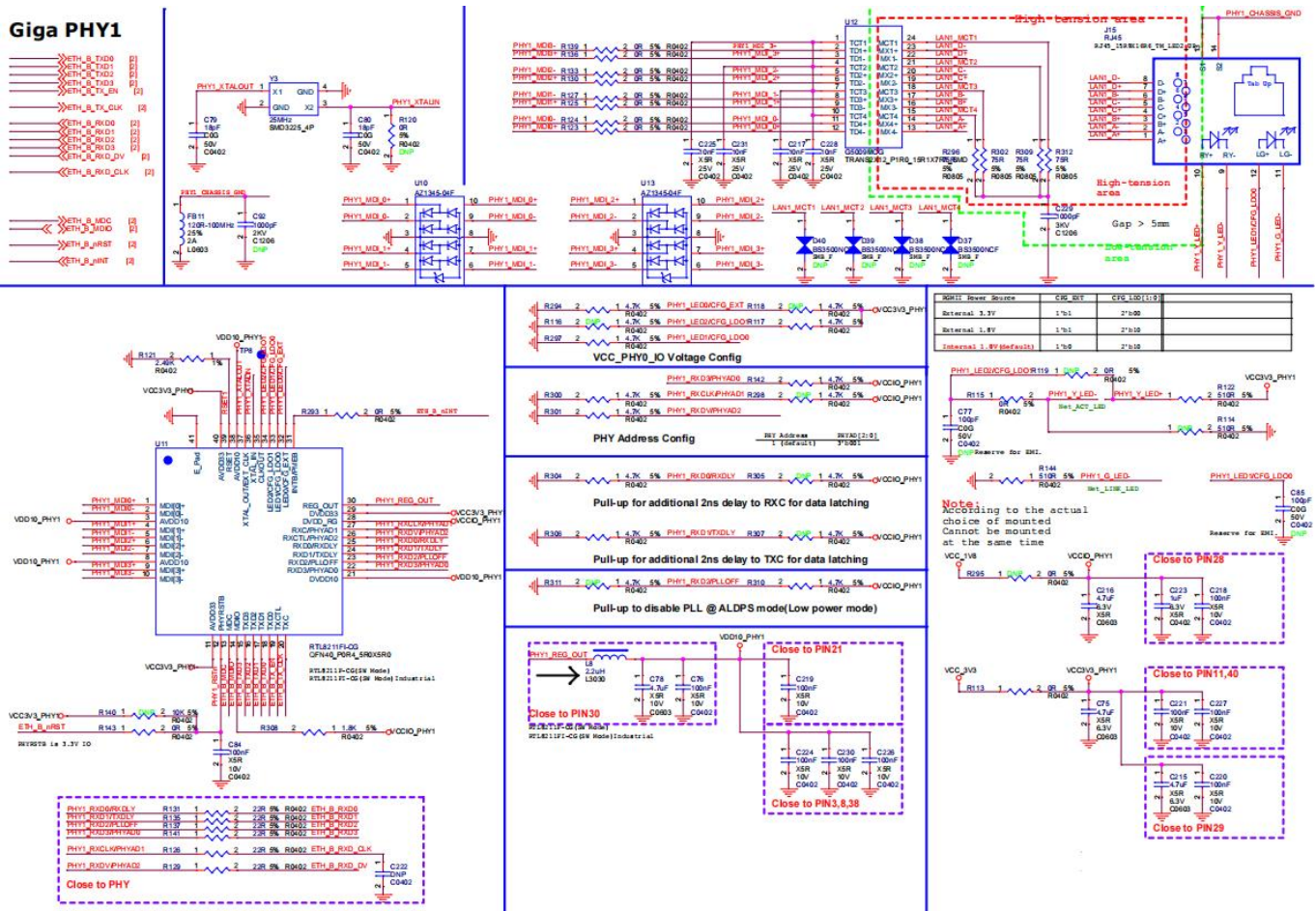
6.3.1 Pin Definitions

Label	Pin	Functional Description	Signal description	Remark
J15	1	ETH_B Differential pairs 0+	LAN1_A+	
	2	ETH_B Differential pairs 0-	LAN1_A-	
	3	ETH_B Differential pairs 1+	LAN1_B+	

	4	ETH_B Differential pairs 1-	LAN1_B-	
	5	ETH_B Differential pairs 2+	LAN1_C+	
	6	ETH_B Differential pairs 2-	LAN1_C-	
	7	ETH_B Differential pairs 3+	LAN1_D+	
	8	ETH_B Differential pairs 3-	LAN1_D-	
	9	Power ground	PHY1_Y_LED-	
	10	LINK Yellow LED	PHY1_Y_LED+	
	11	Power ground	PHY1_G_LED-	
	12	LINK Green LED	PHY1_LED1/CFG_LDO0	
	13	Shell ground	GND	
	14	Shell ground	GND	
J10	1	ETH_A Differential pairs 0+	LAN0_A+	
	2	ETH_A Differential pairs 0-	LAN0_A-	
	3	ETH_A Differential pairs 1+	LAN0_B+	
	4	ETH_A Differential pairs 1-	LAN0_B-	
	5	ETH_A Differential pairs 2+	LAN0_C+	
	6	ETH_A Differential pairs 2-	LAN0_C-	
	7	ETH_A Differential pairs 3+	LAN0_D+	
	8	ETH_A Differential pairs 3-	LAN0_D-	
	9	Power ground	PHY0_Y_LED-	
	10	LINK Yellow LED	PHY0_Y_LED+	
	11	Power ground	PHY0_G_LED-	
	12	LINK Green LED	PHY0_LED1/CFG_LDO0	
	13	Shell ground	GND	
	14	Shell ground	GND	

21

Giga PHY1

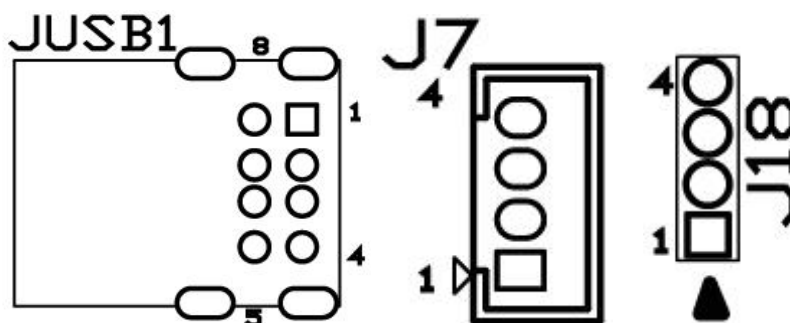


6.3.2 Performance

Parameter	Test method	Min	Typical	Max	Unit	Test Command
TCP Mode speed	Iperf3	-	913	-	Mb/s	Client receive: iperf3 -c x.x.x.x -i 2 -t 60
	Iperf3	-	913	-	Mb/s	Client transmit: iperf3 -c x.x.x.x -i 2 -t 60 -R
UDP Mode speed	Iperf3	-	920	-	Mb/s	client: iperf3 -c 192.168.x.x -t 20 -i 2 -u -b 1000M

6.4 USB Interface (JUSB1、J7、J18)

Four USB HOST and one USB OTG interfaces are designed, including one USB HOST and one USB OTG with Type A interface, and the other three USB HOST are used for USB touch screen interface, USB WiFi module and Mini PCIe interface (connecting 4G module).



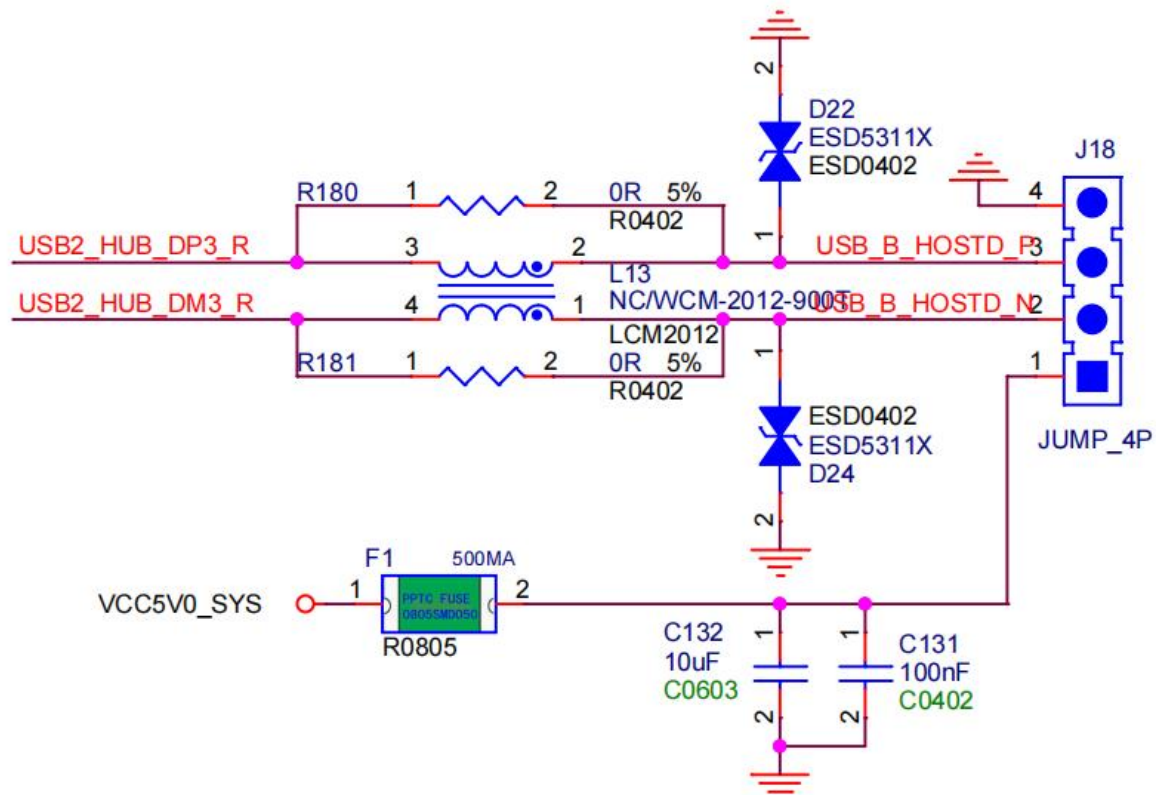
USB2.0 interface schematic

6.4.1 Pin Definitions

Label	Pin	Functional Description	Signal description	Remark
JUSB1 down	1	USB 5V power supply	USB1_HOST_VBUS 5V	5V
	2	USB HOST 1 data -	USB_CON_DOWN_N	USB HOST 1
	3	USB HOST 1 data +	USB_CON_DOWN_P	
	4	Ground signal	GND	
JUSB1 up	1	USB 5V power supply	VCC5V0_USB_OTG 5V	
	2	USB_A_OTG data -	USB_CON_UP_N	USB_A_OTG
	3	USB_A_OTG data +	USB_CON_UP_P	
	4	Ground signal	GND	
J7	1	USB 5V power supply	VCC5V0_SYS	5V
	2	USB HOST 2 data -	USB2_HUB_DM2	USB Touch Screen
	3	USB HOST 2 data +	USB2_HUB_DP2	
	4	Ground signal	GND	
J18	1	USB 5V power supply	VCC5V0_SYS	5V
	2	USB HOST 3 data -	USB2_HUB_DM3	USB WiFi Module
	3	USB HOST 3 data +	USB2_HUB_DP3	
	4	Ground signal	GND	

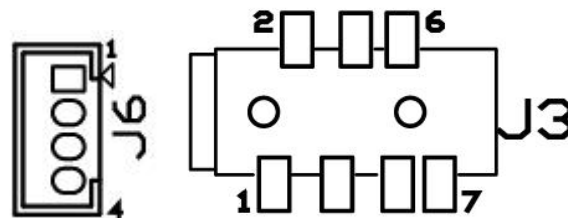


WIFI/BT



6.5 AUDIIO Interface (J6、J3)

Designed to have a 3.5mm standard headphone jack J3 for evaluating audio-related features, the J6 is reserved for speaker output holders.



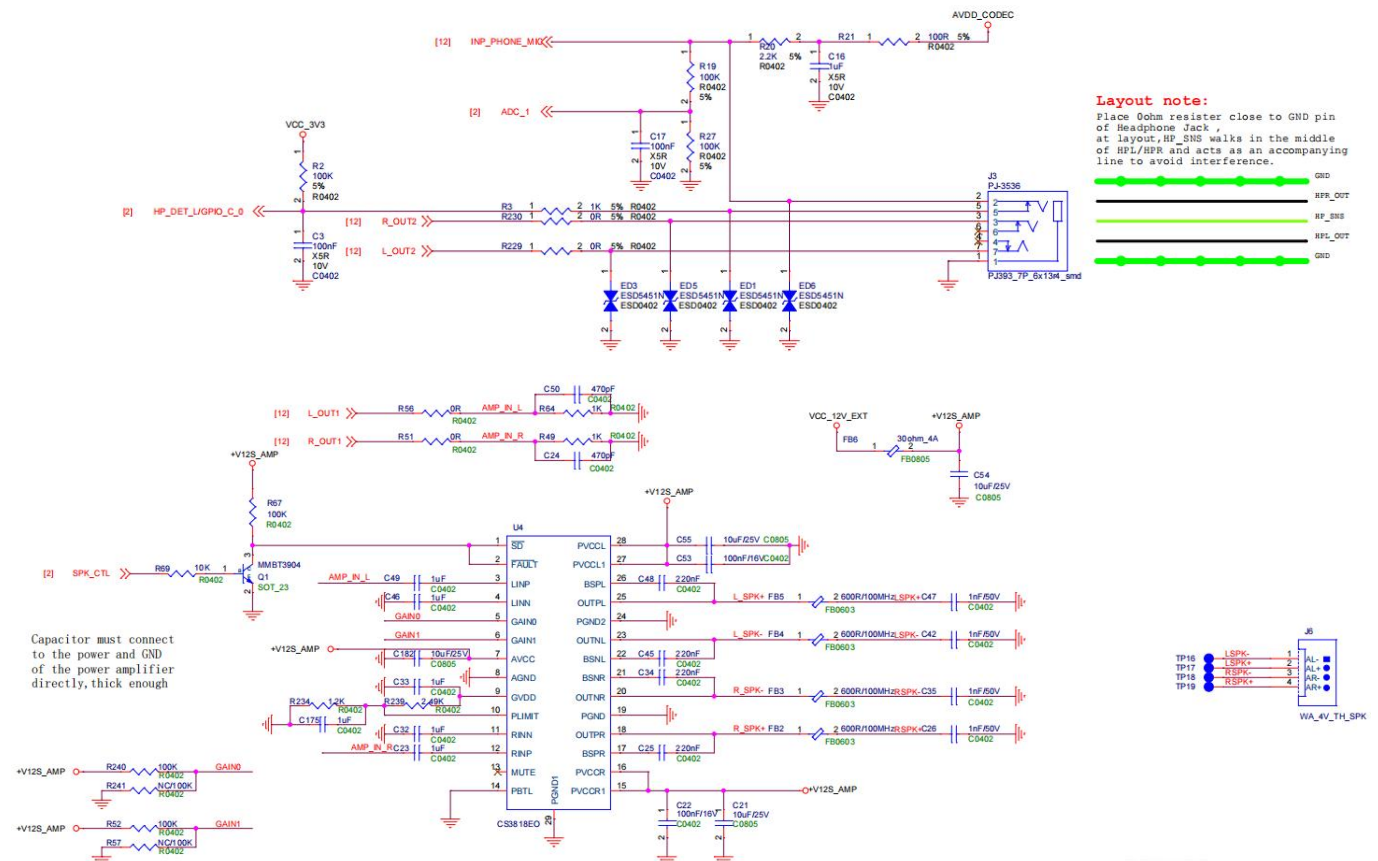
Audio interface schematic

6.5.1 Pin Definitions

Label	Pin	Functional Description	Signal description	Remark
J6	1	Speaker left channel data -	LSPK-	
	2	Speaker left channel data+	LSPK+	

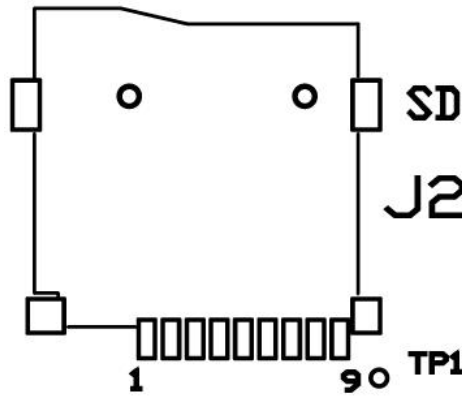
J3	3	Speaker right channel data-	RSPK-	
	4	Speaker right channel data+	RSPK+	
	1	Ground signal	GND	
	2	Microphone input	INP_PHONE_MIC	
	3	Right sound output	R_OUT2	
	4	NC	NC	
	5	Output detection signal	HP_DET_L/GPIO_C_0	
	6	NC	NC	
	7	Left sound output	L_OUT2	

Headphone Jack(4-pole with DET & MIC)



6.6 SD Card Interface (J2)

The development board designs a Micro SD card slot circuit that can be used for system startup, burning, and storage.

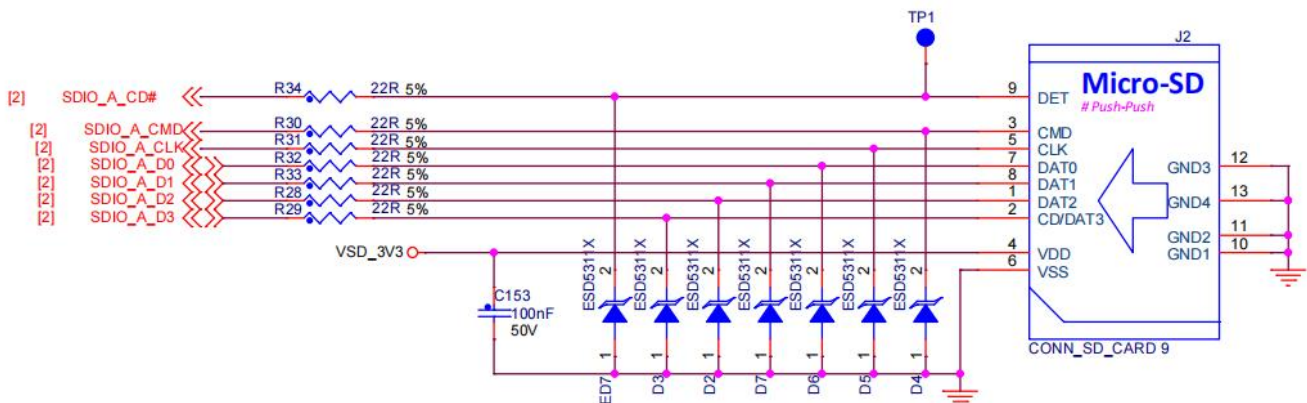


Micro SD Card schematic

6.6.1 Pin Definitions

Label	Pin	Functional Description	Signal description	Remark
J2	1	SDIO_A data 2	SDIO_A_D2	
	2	SDIO_A data 3	SDIO_A_D3	
	3	SDIO_A command	SDIO_A_CMD	
	4	Power supply 3.3V	VSD_3V3	
	5	SDIO_A clocks	SDIO_A_CLK	
	6	Ground signal	GND	
	7	SDIO_A data 0	SDIO_A_D0	
	8	SDIO_A data 1	SDIO_A_D1	
	9	Plug-in card detection	SDIO_A_CD	
	10	Shell ground	GND	
	11	Shell ground	GND	
	12	Shell ground	GND	
	13	Shell ground	GND	

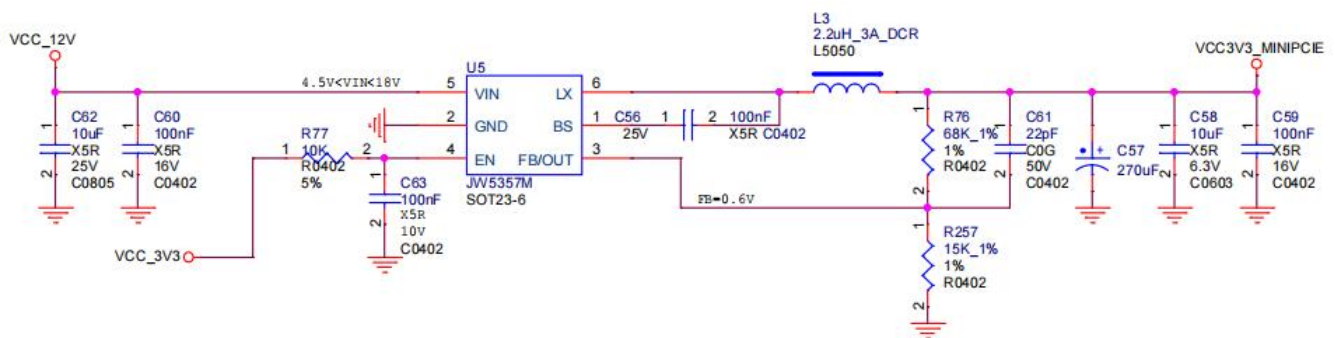
In the debugging process, it is often necessary to carry out program upgrade operations, therefore, it is necessary to add a TF card interface on the development board, the circuit is shown in Figure.

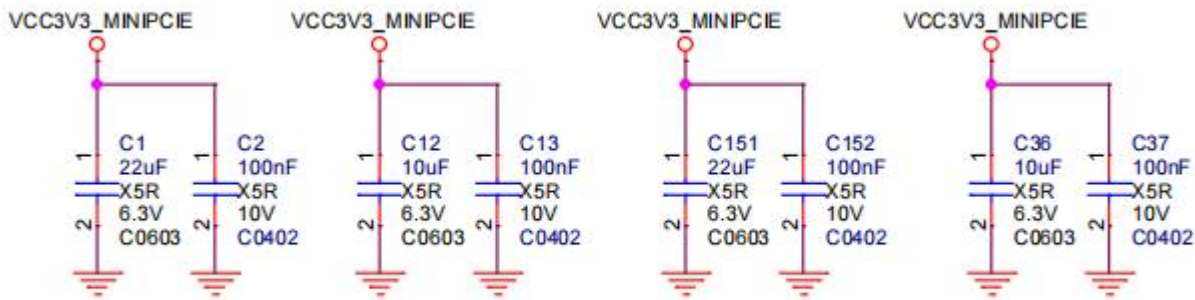




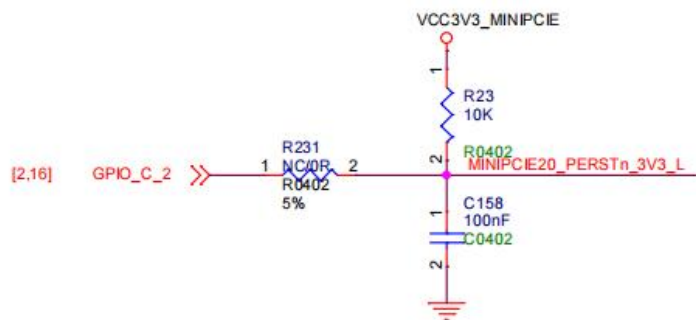
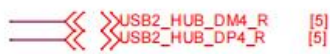
4	Ground signal	GND	
5	NC	NC	
6	NC	NC	
7	NC	NC	
8	SIM card power supply	UIM_PWR	
9	Ground signal	GND	
10	SIM card data signal	UIM_DATA	
11	NC	NC	
12	SIM card clock	UIM_CLK	
13	NC	NC	
14	SIM card reset	UIM_RESET	
15	Ground signal	GND	
16	NC	NC	
17	NC	NC	
18	Ground signal	GND	
19	NC	NC	
20	NC	NC	
21	Ground signal	GND	
22	MiniPCle reset	MINIPCLIE20_PERSTn_3V3_L	
23	NC	NC	
24	Power supply 3.3V	VCC3V3_MINIPCLIE	
25	NC	NC	
26	Ground signal	GND	
27	地信号	GND	
28	NC	NC	
29	Ground signal	GND	
30	NC	NC	
31	NC	NC	

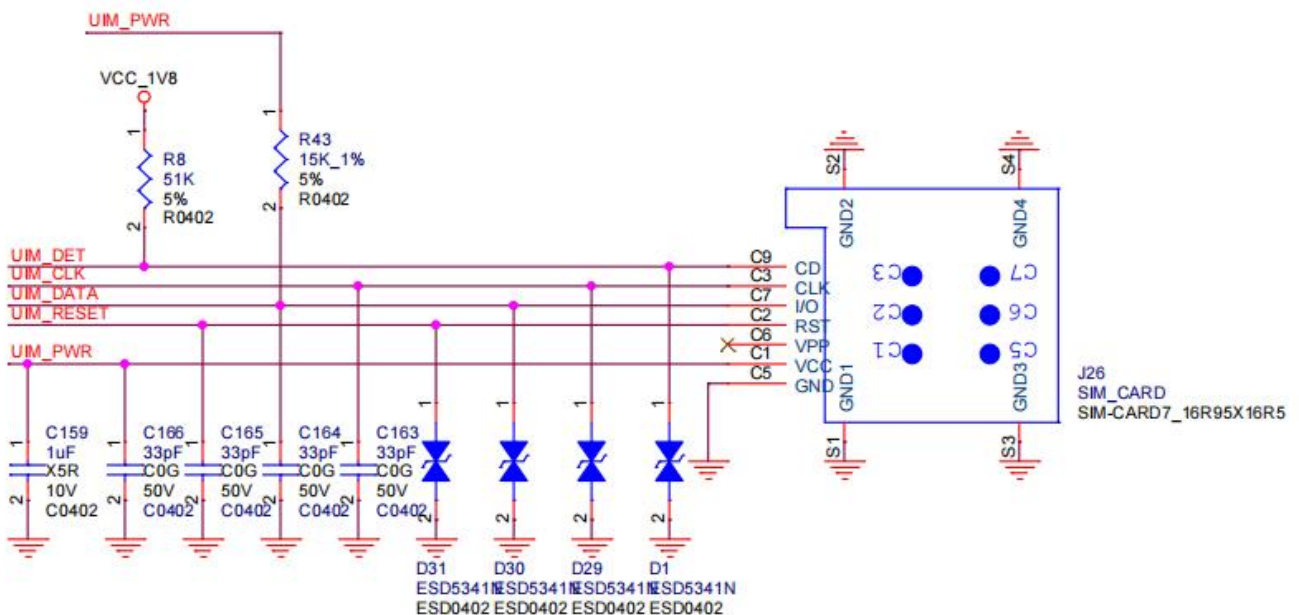
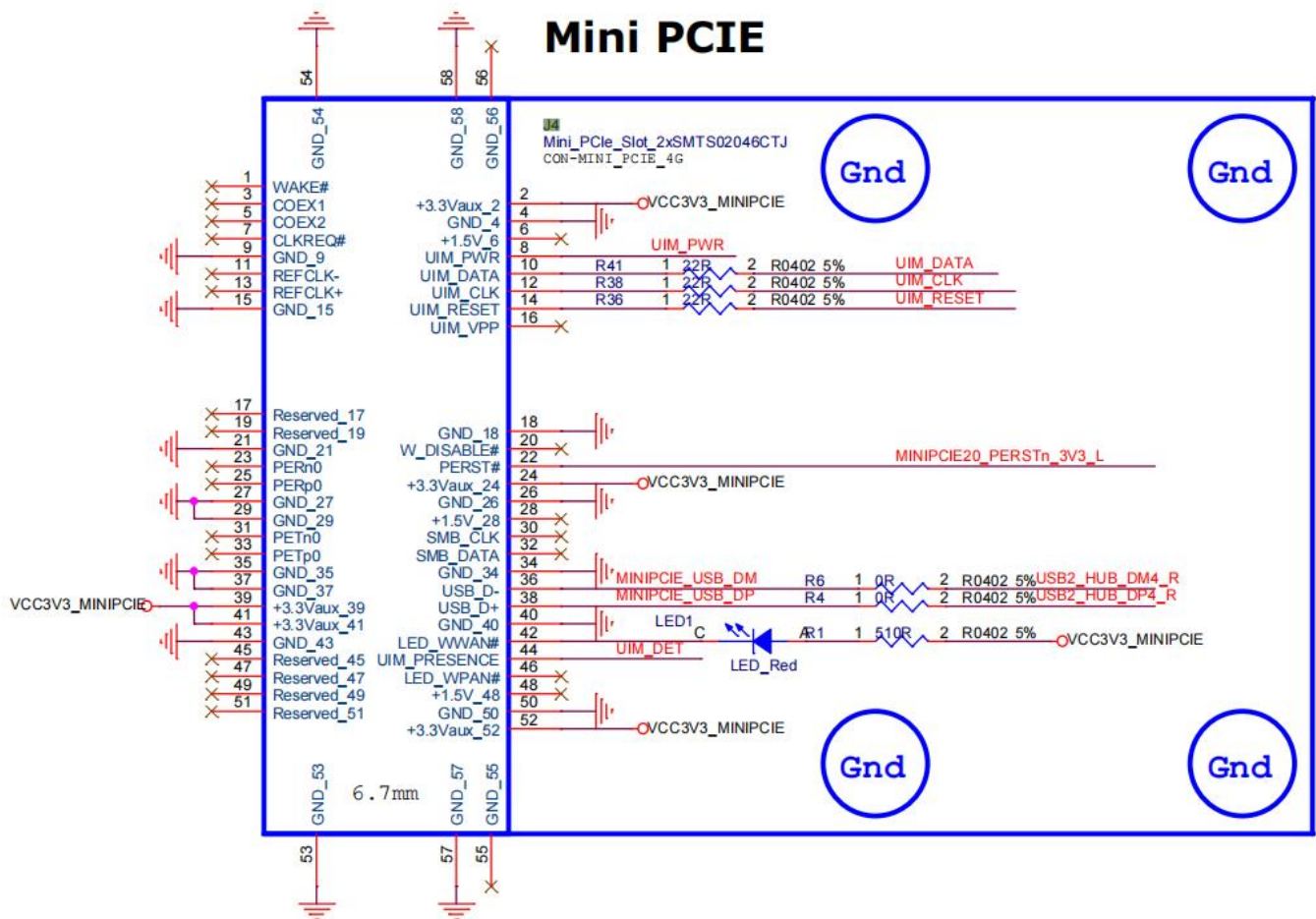
32	NC	NC	
33	NC	NC	
34	Ground signal	GND	
35	Ground signal	GND	
36	USB2.0 HUB 4 data -	MINI_PCIE_USB_DM	USB2_HUB_DM4
37	Ground signal	GND	
38	USB2.0 HUB 4 data +	MINI_PCIE_USB_DP	USB2_HUB_DP4
39	Power supply 3.3V	VCC3V3_MINIPCIE	
40	Ground signal	GND	
41	Power supply 3.3V	VCC3V3_MINIPCIE	
42	LED power supply	LED_WWAN	
43	Ground signal	GND	
44	SIM card detection signal	UIM_DET	
45	NC	NC	
46	NC	NC	
47	NC	NC	
48	NC	NC	
49	NC	NC	
50	Ground signal	GND	
51	NC	NC	
52	Power supply 3.3V	VCC3V3_MINIPCIE	





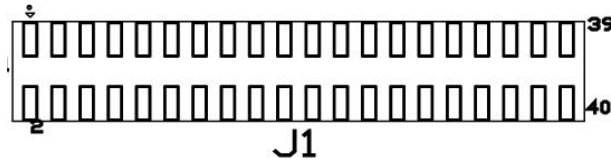
Place capacitors closed to PCIe slot





6.8 GPIO/QSPI/UART/I2C Interface (J1)

A 2.0-spacing 40 PIN twin row needle was designed on which 5V power supply, 3.3V power supply, 4*UART, 1*QSPI, 1*SPI, 1*I2C and several GPIO signals were defined.

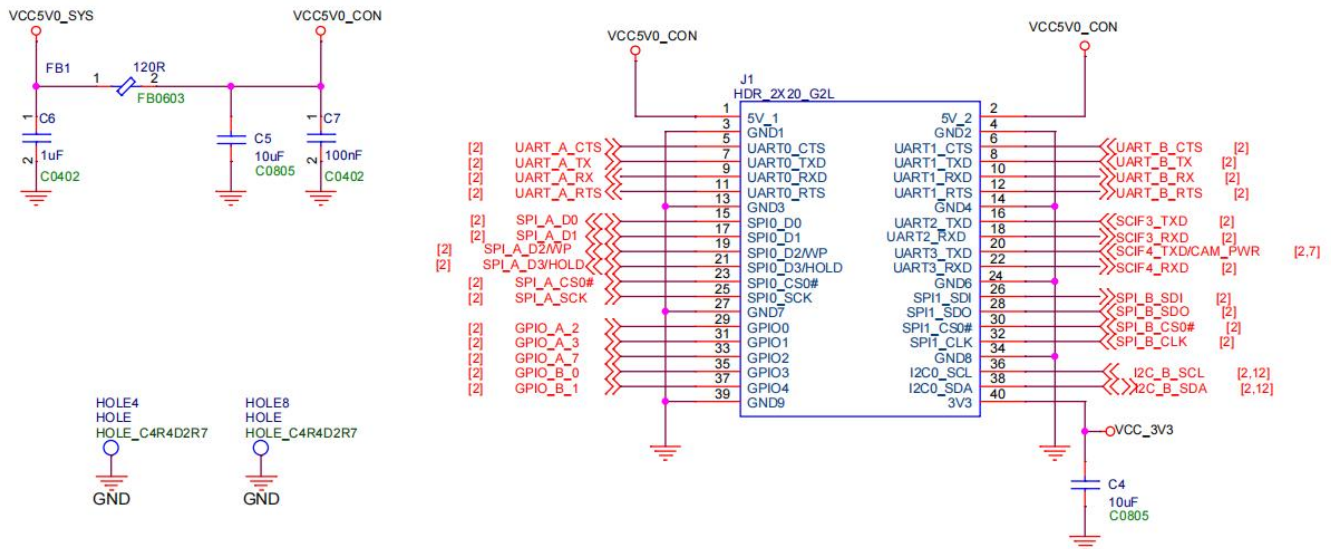


GPIO/QSPI/UART/I2C interface schematics

6.8.1 Pin Definitions

Label	Pin	Functional Description	Signal description	Remark
J1	1	Output power supply 5V	VCC5V0_CON	
	2	Output power supply 5V	VCC5V0_CON	
	3	Ground signal	GND	
	4	Ground signal	GND	
	5	UART_A Clear to send	UART_A_CTS	
	6	UART_B Clear to send	UART_B_CTS	
	7	UART_A send data	UART_A_TX	
	8	UART_B send data	UART_B_TX	
	9	UART_A receive data	UART_A_RX	
	10	UART_B receive data	UART_B_RX	
	11	UART_A Request to send	UART_A_RTS	
	12	UART_B Request to send	UART_B_RTS	
	13	Ground signal	GND	
	14	Ground signal	GND	
	15	QSPI_A data 0	SPI_A_D0	
	16	UART3 send data	SCIF3_TXD	
	17	QSPI_A Data input output 1/Data output	SPI_A_D1	
	18	UART3 receive data	SCIF3_RXD	
	19	QSPI_A Data input output 2/Write protect input	SPI_A_D2/WP	

20	UART4 send data	SCIF4_TXD/CAN_PWR	
21	QSPI_A Data input output 3/Hold or Reset input	SPI_A_D3/HOLD	
22	UART4 receive data	SCIF4_RXD	
23	QSPI_A Chip select input	SPI_A_CS0	
24	Ground signal	GND	
25	QSPI_A clock	SPI_A_SCK	
26	SPI_B Master out slave in	SPI_B_SDI(MOSI)	
27	Ground signal	GND	
28	SPI_B Master in slave out	SPI_B_SDO(MISO)	
29	GPIO	GPIO_A_2	
30	SPI_B Chip select input	SPI_B_CS0	
31	GPIO	GPIO_A_3	
32	SPI_B synchronous clock signal	SPI_B_CLK	
33	GPIO	GPIO_A_7	
34	Ground signal	GND	
35	GPIO	GPIO_B_0	
36	I2C_B clock	I2C_B_SCL	
37	GPIO	GPIO_B_1	
38	I2C_B data	I2C_B_SDA	
39	Ground signal	GND	
40	Output power supply 3.3V	VCC_3V3	



6.9 Microphone Interface (MIC1)

Design of the road microphone interface



Microphone connector schematic

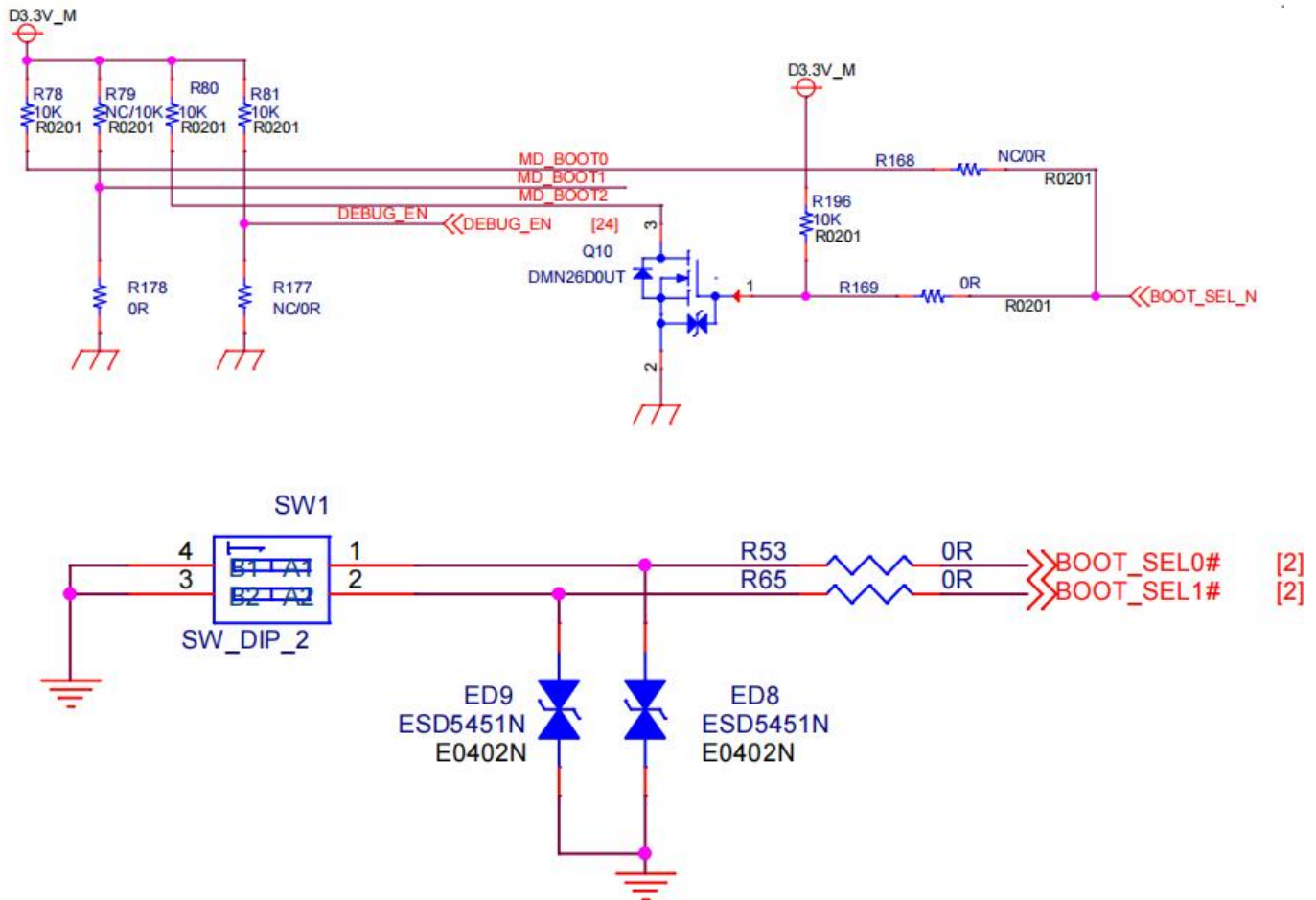
6.9.1 Pin Definitions

Label	Pin	Functional Description	Signal description	Remark
MIC1	1	Microphone input signal+	MIC2P	EM6027-32BC6.8nF&R330-G
	2	Microphone input signal-	MIC2N	

36

3) The core board is equipped with SPI device, the default boot from SPI flash.

In order to support different boot modes, it is necessary to pull up and down the BOOT pin on the base board, the circuit diagram is shown below.



BOOT pin configuration circuit

BOOT_SEL0# of SW1 corresponds to BOOT_SET_N of the core board, and BOOT_SEL1# is empty.

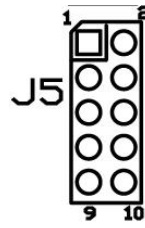
The currently supported boot mode are configured as shown in the following table.

SW1 Status	Boot mode
01	eMMC
11	Serial port

Note: 0 indicates SW1 ends are disconnected; 1 identifies SW1 ends are shorted.

6.11 JTAG Interface (J5)

A JTAG interface is reserved for system debugging.

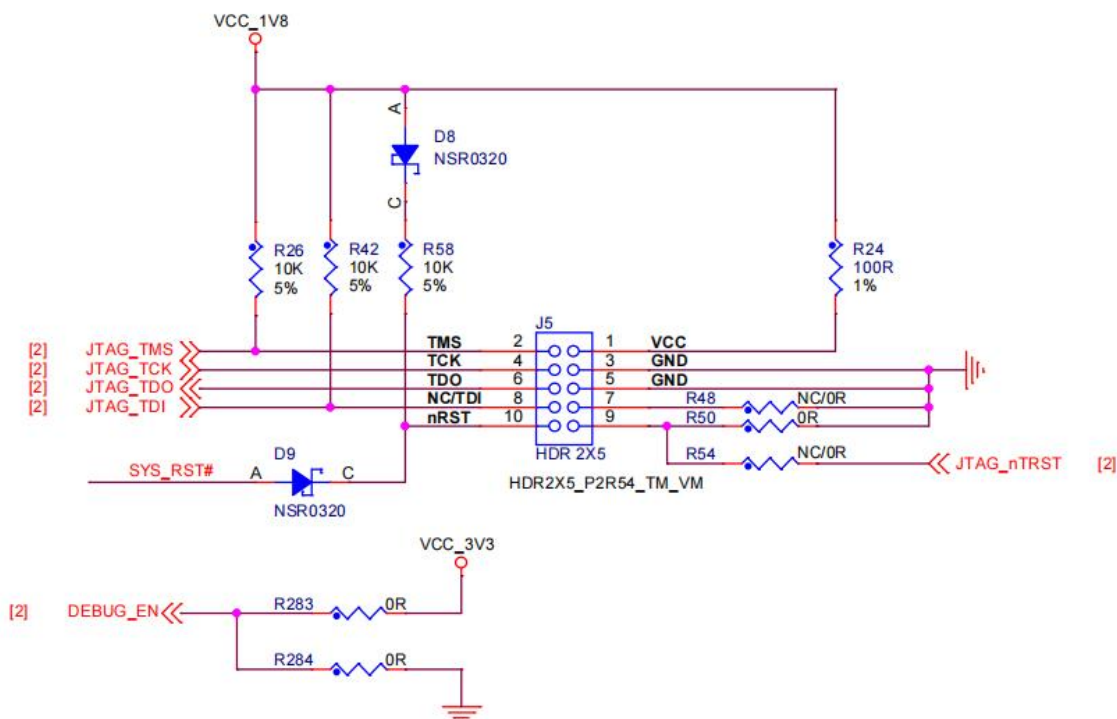


JTAG interface schematic

6.11.1 Pin Definitions

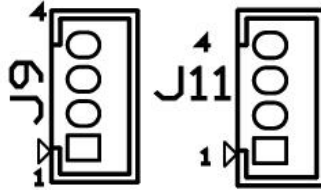
Label	Pin	Functional Description	Signal description	Remark
J5	1	Power supply 1.8V	VCC	1.8V
	2	Mode selection signal	JTAG_TMS	
	3	Ground signal	GND	
	4	Time cycle clock	JTAG_TCK	
	5	Ground signal	GND	
	6	Data output signal	JTAG_TDO	
	7	NC	NC	
	8	Test data input	JTAG_TDI	
	9	Ground signal	GND	
	10	System Reset	SYS_RST#	

JTAG Debug



6.12 UART Serial Interface (J9、J11)

Two UART serial ports are designed for debugging the system A55 core and M33 core.

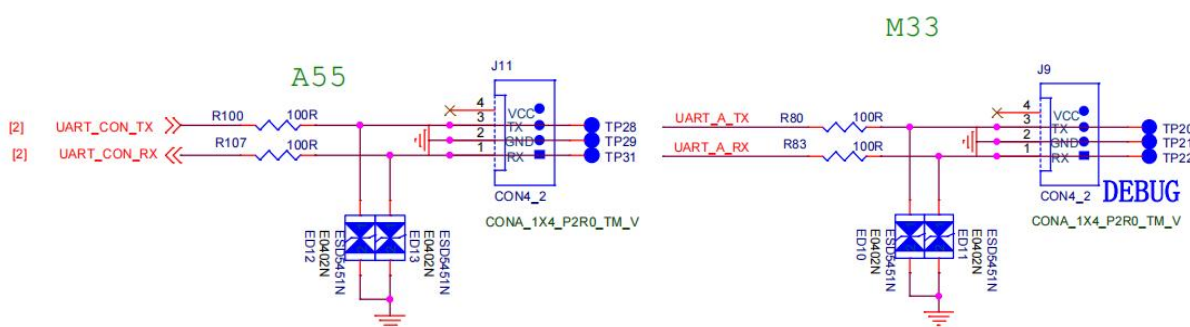


UART serial port schematic

6.12.1 Pin Definitions

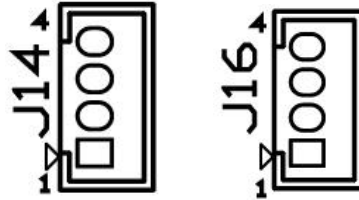
Label	Pin	Functional Description	Signal description	Remark
J9	1	NC	NC	M33 core debugging serial port
	2	UART_A send data	UART_A_TX	
	3	Ground signal	GND	
	4	UART_A receive data	UART_A_RX	
J11	1	NC	NC	A55 core debugging serial port
	2	UART_CON send data	UART_CON_TX	
	3	Ground signal	GND	
	4	UART_CON receive data	UART_CON_RX	

The DB-G2L V2 can only be used for program burning and system debugging through the SCIF0(UART_CON) serial port, so the interface must be pinned out on the backplane, and the interface circuit is shown in the figure.



6.13 CAN Interface (J14, J16)

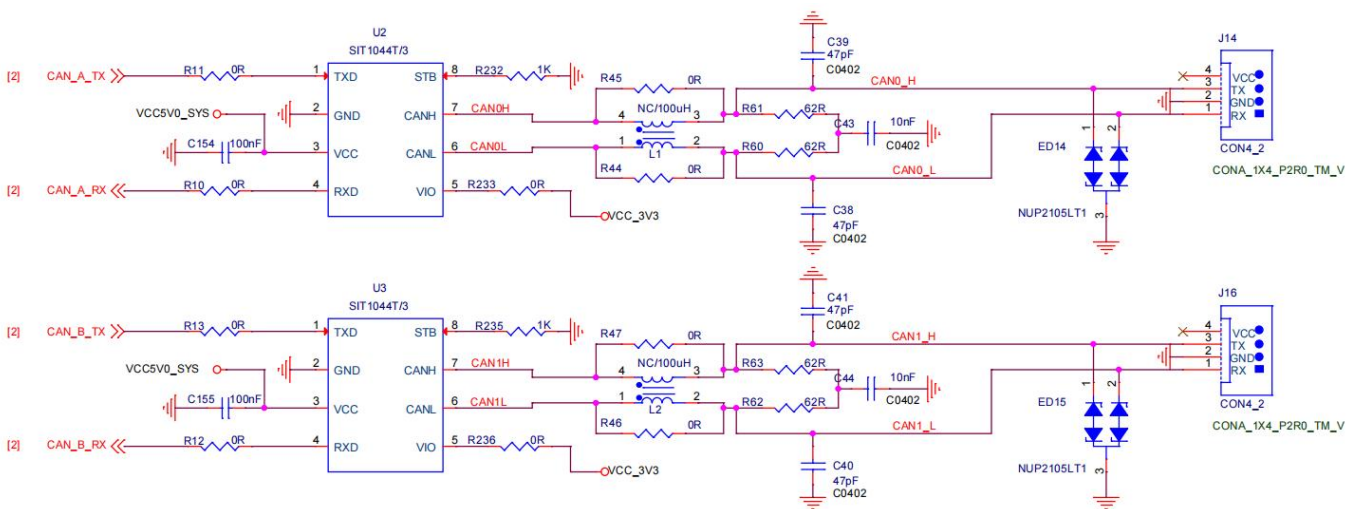
The development board is designed supporting 2 CAN channels, which is convenient for users to evaluate related functions.



CAN interface schematic

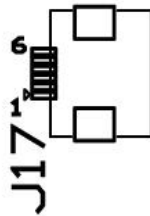
6.13.1 Pin Definitions

Label	Pin	Functional Description	Signal description	Remark
J14	1	CAN0_L	CAN0_L	
	2	Ground signal	GND	
	3	CAN0_H	CAN0_H	
	4	NC	NC	
J16	1	CAN1_L	CAN1_L	
	2	Ground signal	GND	
	3	CAN1_H	CAN1_H	
	4	NC	NC	



6.14 I2C Touch Panel Interface (J17)

Designed all the way I2C capacitive touch screen interface, can be connected to capacitive touch screen, the development board system driver has been configured as a seven-inch capacitive touch screen

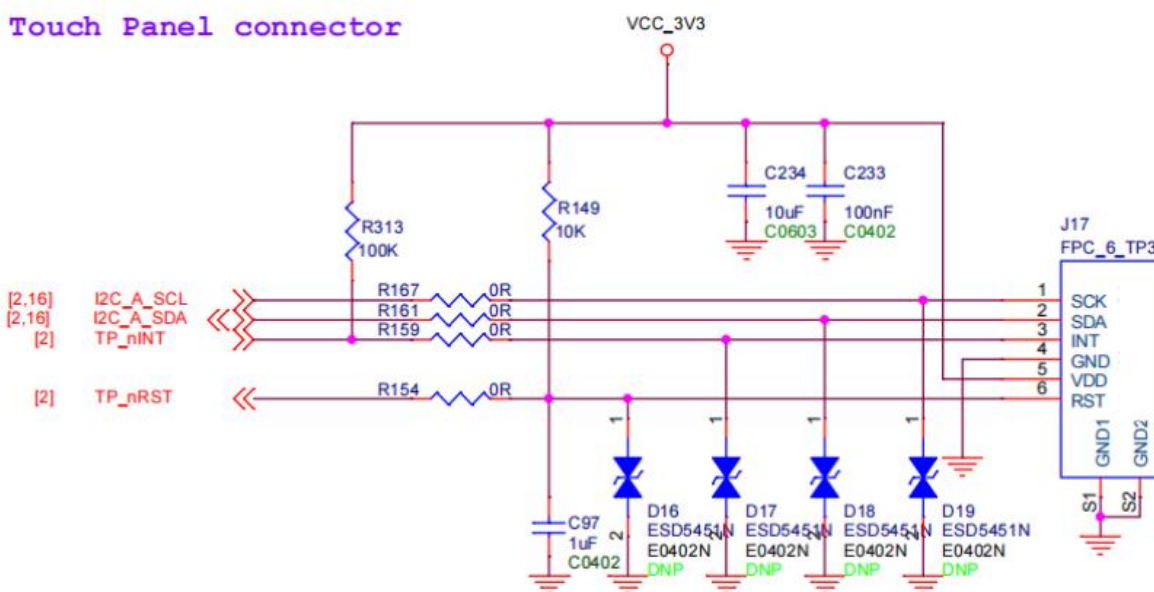


I2C Capacitive touch screen interface schematic

6.14.1 Pin Definitions

Label	Pin	Functional Description	Signal description	Remark
J17	1	I2C_A Clock	I2C_A_SCL	
	2	I2C_A Data	I2C_A_SDA	
	3	Touch screen Interrupt	TP_nINT	
	4	Ground signal	GND	
	5	3.3V Power supply	VCC_3V3	
	6	Touch screen reset	TP_nRST	

Touch Panel connector



6.15 RTC Battery (CG1)

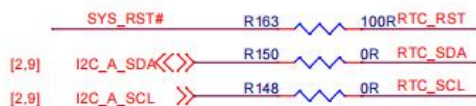
Design a rechargeable 3V RTC battery.



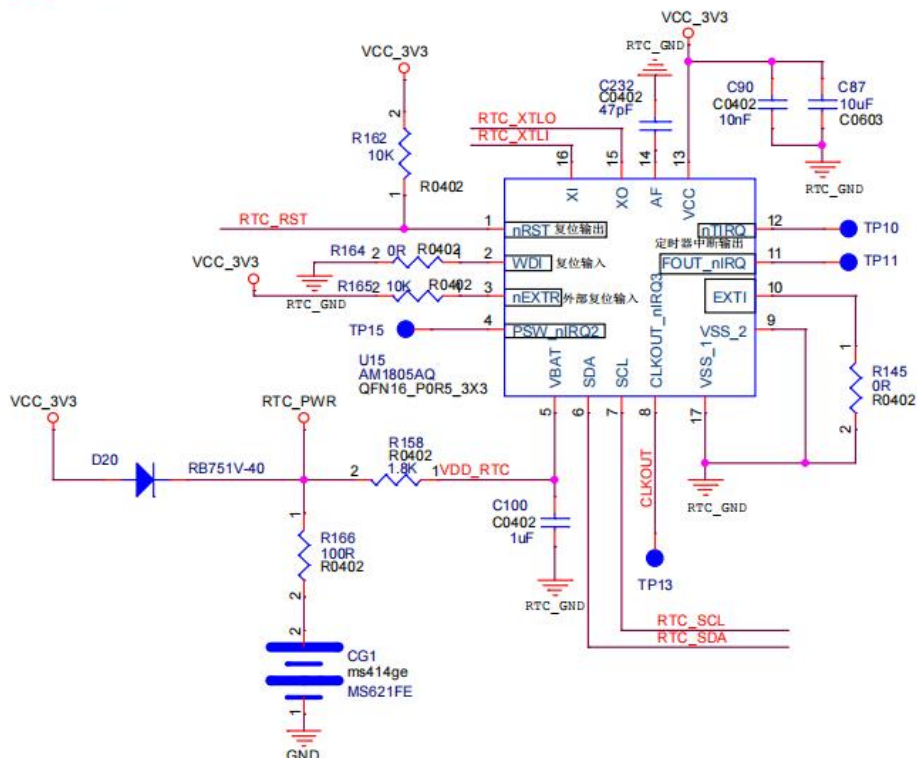
RTC 3V battery

6.15.1 Pin Definitions

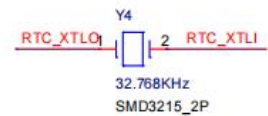
Label	Pin	Functional Description	Signal description	Remark
CG1	1	Power ground	-	MS621FE
	2	RTC power supply 3V	-	



Operating voltage :1.5~3.6 V
VCC System Power Voltage: -0.3~3.8 V



(-40--85°C)

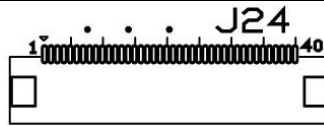


AM1805 Addr:0x68



6.16 DSI Interface (J24)

Designed a DSI interface, can be connected to the MIPI DSI interface model WD101HKM40AB-E6-05/HK101TLED-M-KM01 display, the maximum resolution of 1920 * 1080.

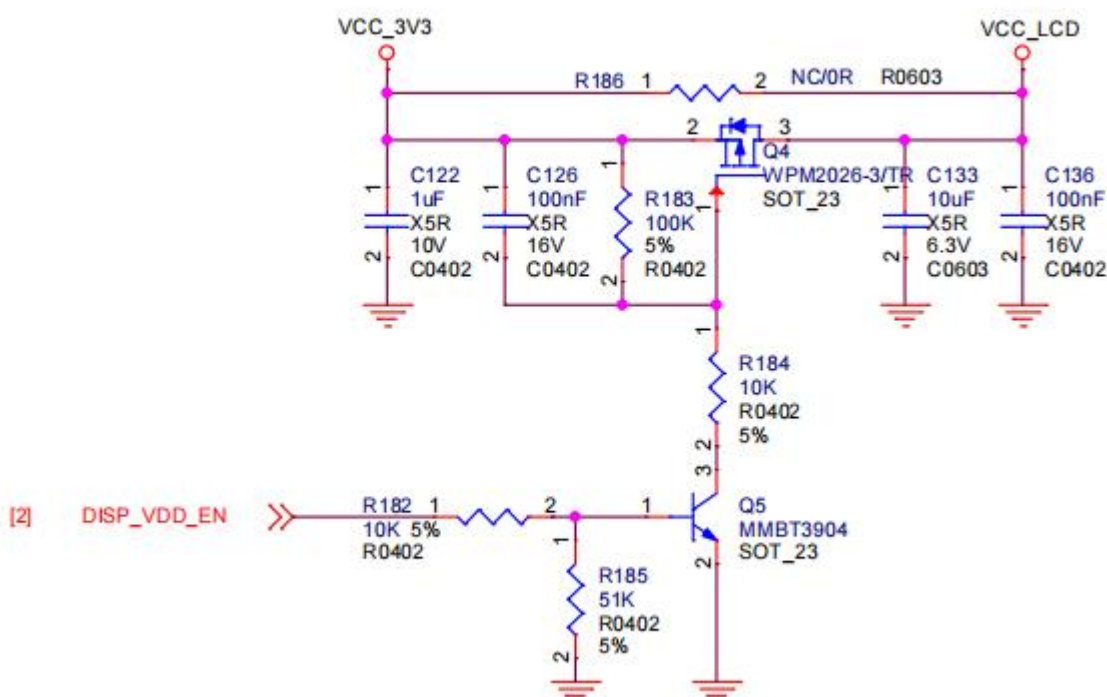
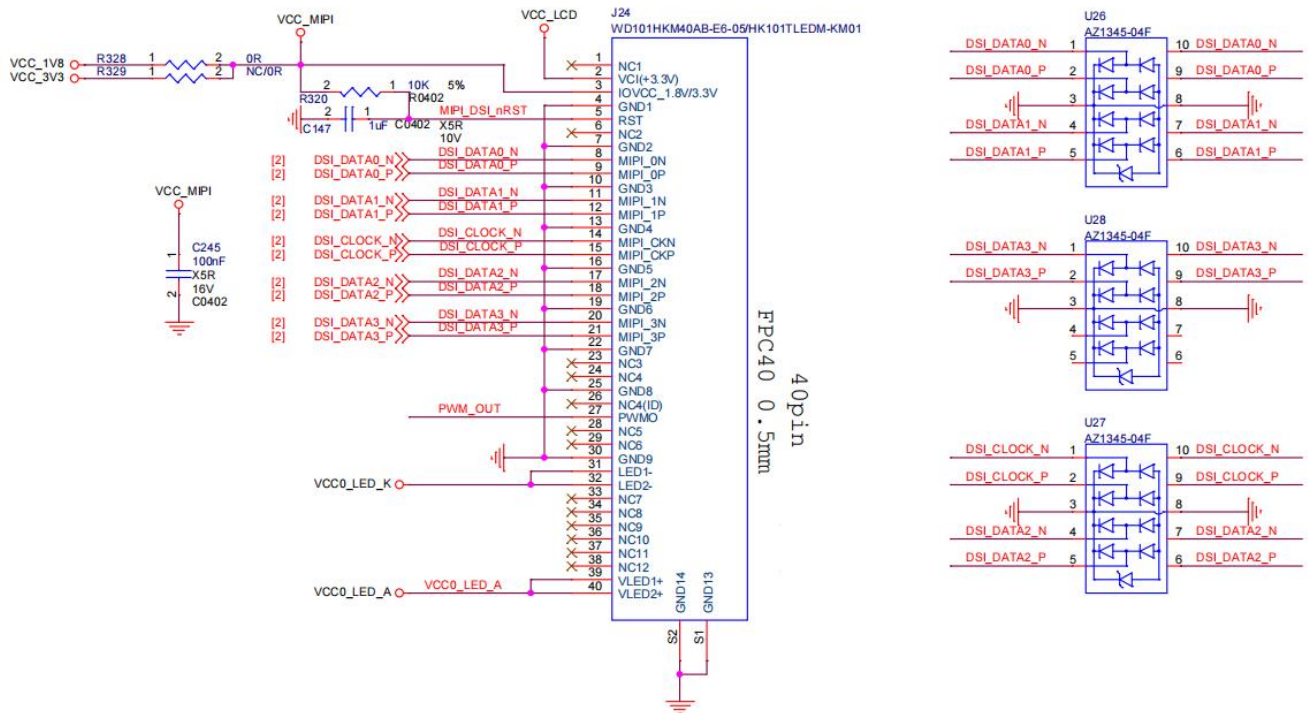


MIPI DSI display interface schematic

6.16.1 Pin Definitions

Label	Pin	Functional Description	Signal description	Remark
J24	1	NC	NC	
	2	Power supply 3.3V	VCC_LED	3.3V
	3	Power supply 1.8V/3.3V	VCC_1V8/3V3	1.8V/3.3V
	4	Ground signal	GND	
	5	DSI reset signal	MIPI_DSI_nRST	
	6	NC	NC	
	7	Ground signal	GND	
	8	DSI interface data 0-	DSI_DATA0_N	
	9	DSI interface data 0+	DSI_DATA0_P	
	10	Ground signal	GND	
	11	DSI interface data1-	DSI_DATA1_N	
	12	DSI interface data1+	DSI_DATA1_P	
	13	Ground signal	GND	
	14	DSI interface clock-	DSI_CLOCK_N	
	15	DSI interface clock+	DSI_CLOCK_P	
	16	Ground signal	GND	
	17	DSI interface data2-	DSI_DATA2_N	
	18	DSI interface data2+	DSI_DATA2_P	
	19	Ground signal	GND	
	20	DSI interface data3-	DSI_DATA3_N	
	21	DSI interface data3+	DSI_DATA3_P	
	22	Ground signal	GND	
	23	NC	NC	
	24	NC	NC	
	25	Ground signal	GND	
	26	NC	NC	
	27		PWM_OUT	
	28	NC	NC	
	29	NC	NC	
	30	Ground signal	GND	
	31	LED backlight power supply-	VCC0_LED_K	
	32	LED backlight power supply-	VCC0_LED_K	
	33	NC	NC	
	34	NC	NC	
	35	NC	NC	

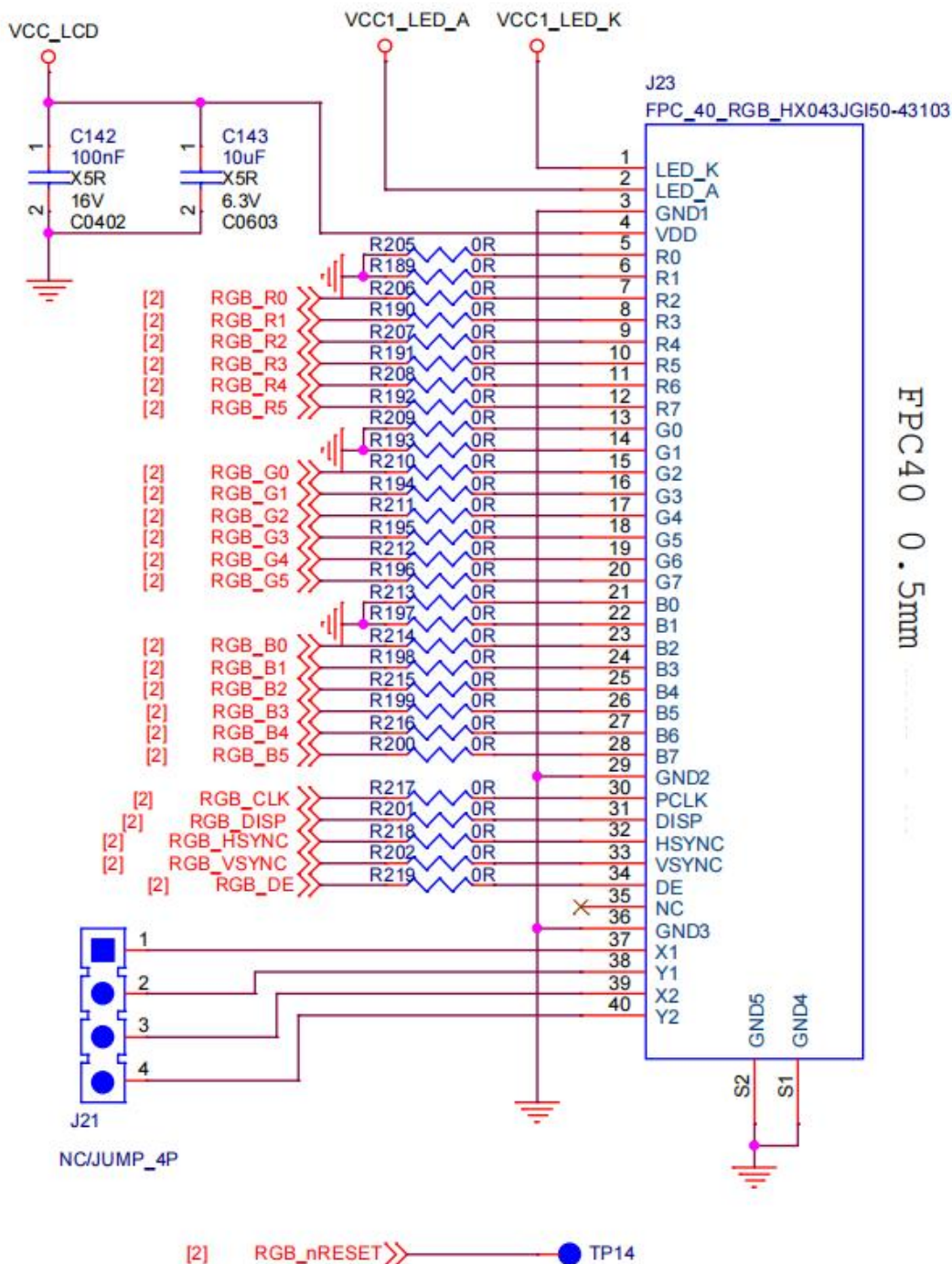
	36	NC	NC	
	37	NC	NC	
	38	NC	NC	
	39	LED backlight power supply+	VCC0_LED_A	
	40	LED backlight power supply+	VCC0_LED_A	





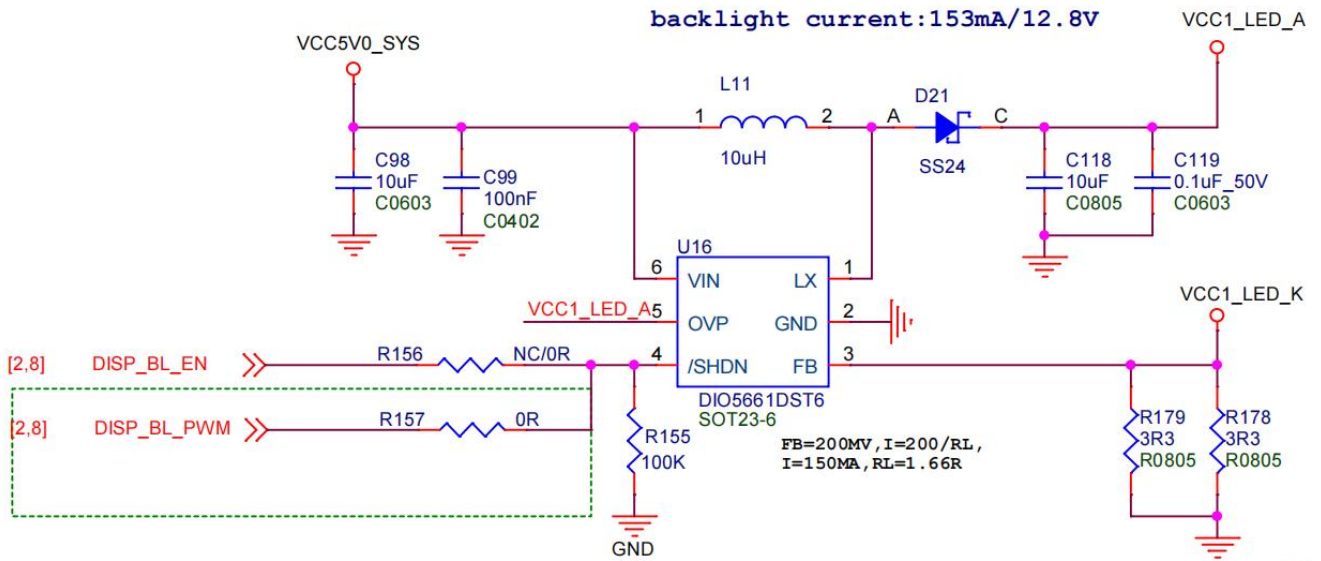
9	Red data bus 2	RGB_R2	
10	Red data bus 3	RGB_R3	
11	Red data bus 4	RGB_R4	
12	Red data bus 5	RGB_R5	
13	Ground signal	GND	
14	Ground signal	GND	
15	Green data bus 0	RGB_G0	
16	Green data bus 1	RGB_G1	
17	Green data bus 2	RGB_G2	
18	Green data bus 3	RGB_G3	
19	Green data bus 4	RGB_G4	
20	Green data bus 5	RGB_G5	
21	Ground signal	GND	
22	Ground signal	GND	
23	Blue data bus 0	RGB_B0	
24	Blue data bus 1	RGB_B1	
25	Blue data bus 2	RGB_B2	
26	Blue data bus 3	RGB_B3	
27	Blue data bus 4	RGB_B4	
28	Blue data bus 5	RGB_B5	
29	Ground signal	GND	
30	Data clock signal	RGB_CLK	Fro controlling data transfer
31	Standby mode select	RGB_DISP	
32	Line SYNC signal	RGB_HSYNC	For controlling the horizontal synchronization of images
33	Frame SYNC signal	RGB_VSYNC	For controlling the vertical synchronization of the image
34	Data enable input	RGB_DE	
35	NC	NC	
36	Ground signal	GND	

	37	NC	NC	
	38	NC	NC	
	39	NC	NC	
	40	NC	NC	



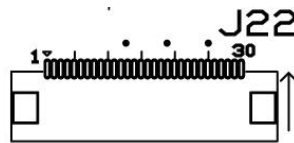
LED Backlight

backlight current:153mA/12.8V



6.18 CSI Camera Interface (J22)

Designed with a MIPI CSI camera interface, FPC interface for CSI_ZH13850-ZH-001 model cameras.

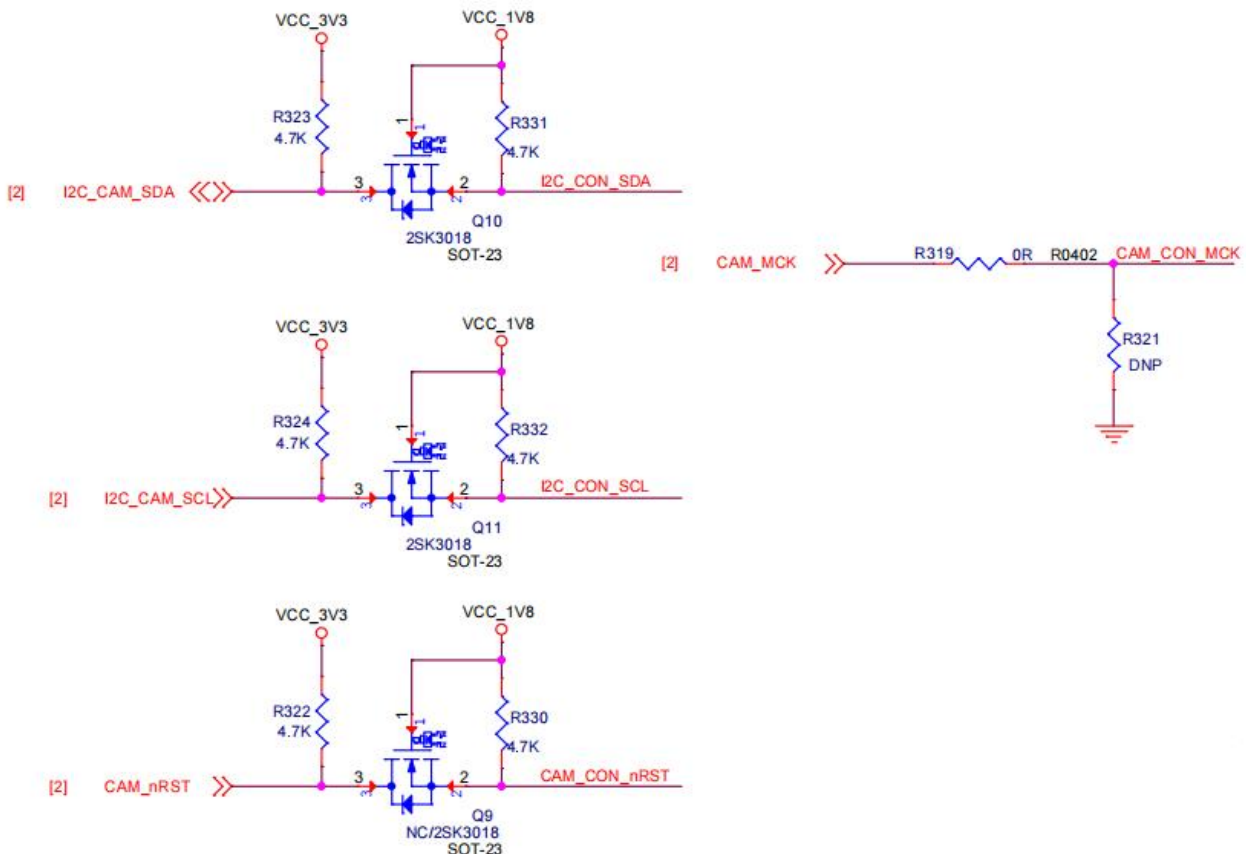
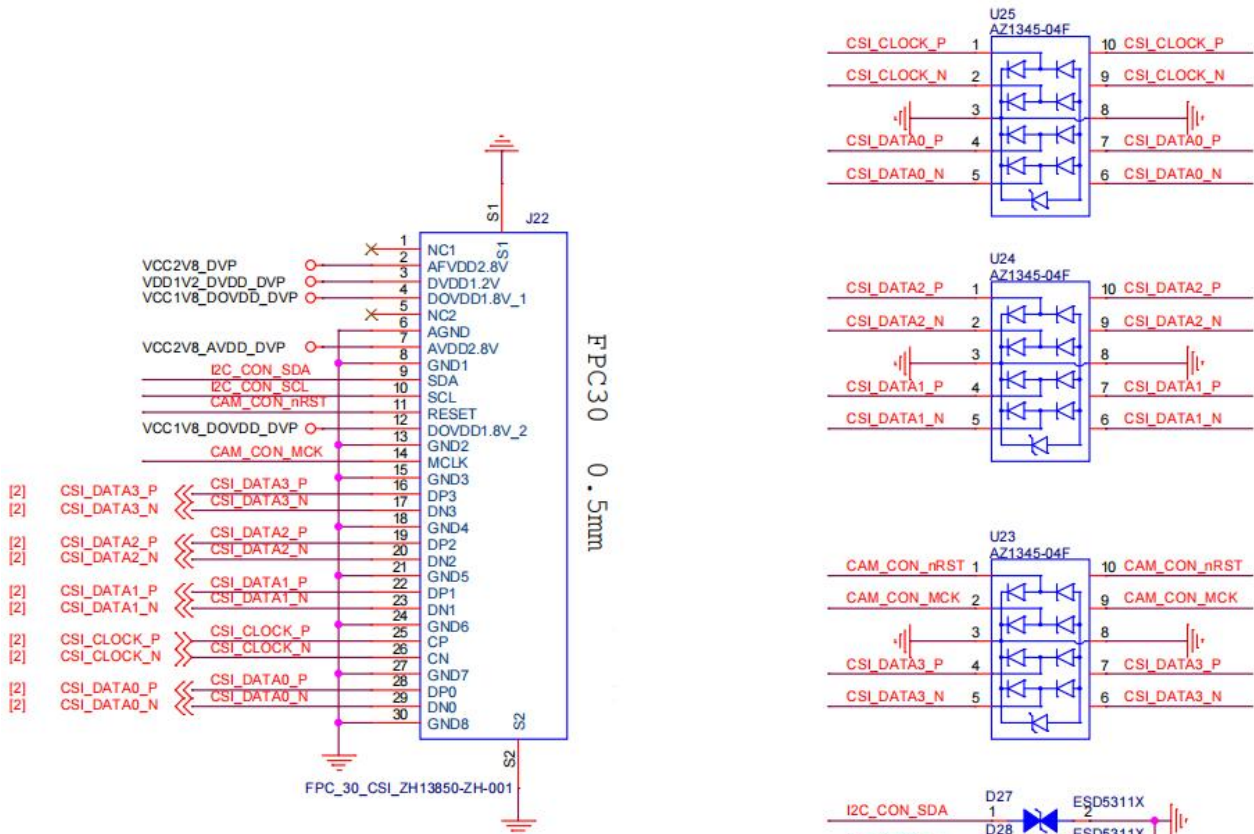


CSI Camera interface schematic

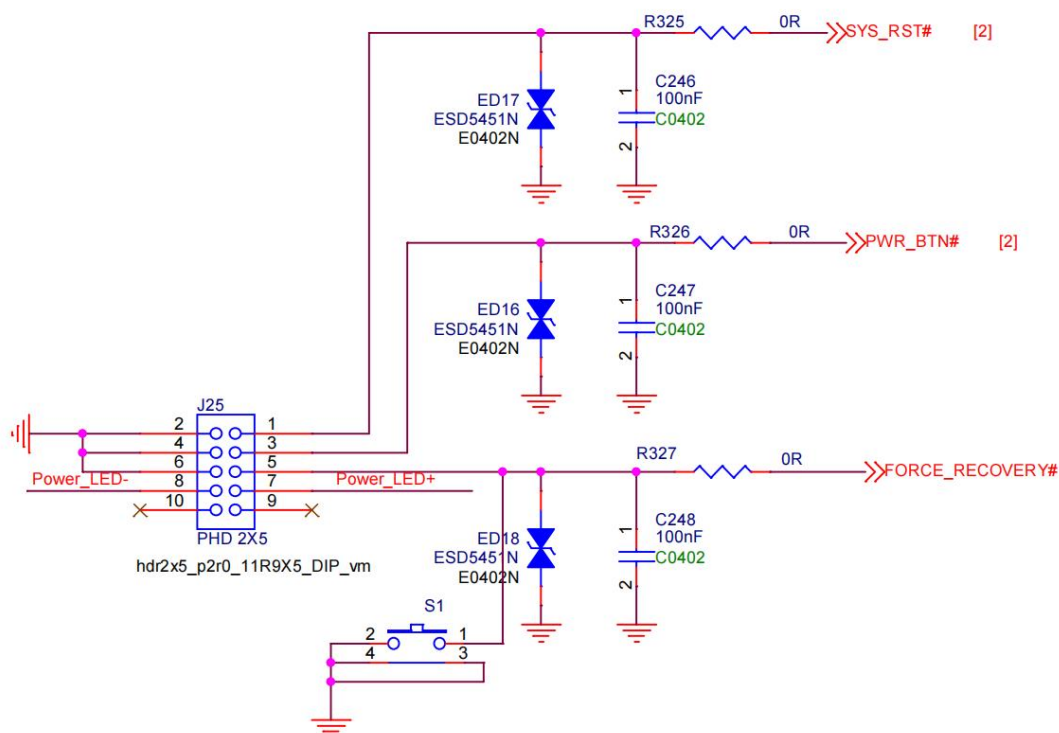
6.18.1 Pin Definitions

Label	Pin	Functional Description	Signal description	Remark
J22	1	NC	NC	
	2	Power supply 2.8V	VCC2V8_DVP	
	3	Power supply 1.2V	VDD1V2_DVDD_DVP	
	4	Power supply 1.8V	VCC1V8_DOVDD_DVP	
	5	NC	NC	
	6	Ground signal	GND	
	7	Power supply 2.8V	VCC2V8_AVDD_DVP	
	8	Ground signal	GND	
	9	I2C_CON data	I2C_CON_SDA	

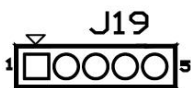
10	I2C_CON clock	I2C_CON_SCL	
11	Reset	CAM_CON_nRST	
12	Power supply 1.8V	VCC1V8_DOVDD_DVP	
13	Ground signal	GND	
14	CSI master clock signal	CAM_CON_MCK	
15	Ground signal	GND	
16	CSI interface data 3+	CSI_DATA3_P	
17	CSI interface data 3-	CSI_DATA3_N	
18	Ground signal	GND	
19	CSI interface data 2+	CSI_DATA2_P	
20	CSI interface data 2 -	CSI_DATA2_N	
21	Ground signal	GND	
22	CSI interface data 1+	CSI_DATA1_P	
23	CSI interface data 1-	CSI_DATA1_N	
24	Ground signal	GND	
25	CSI interface clock+	CSI_CLOCK_P	
26	CSI interface clock-	CSI_CLOCK_N	
27	Ground signal	GND	
28	CSI interface data 0+	CSI_DATA0_P	
29	CSI interface data 0-	CSI_DATA0_N	
30	Ground signal	GND	







6.20 PoE PD 12V Power Supply Output Interface(J19)

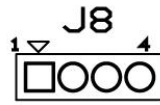


PoE PD 12V power supply output interface schematic

6.20.1 Pin Definitions

Label	Pin	Functional Description	Signal description	Remark
J19	1	Power Ground	GND	
	2	DC 12 +	VCC12_POE	
	3	NC	NC	
	4	DC12 +	VCC12_POE	
	5	Power Ground	GND	

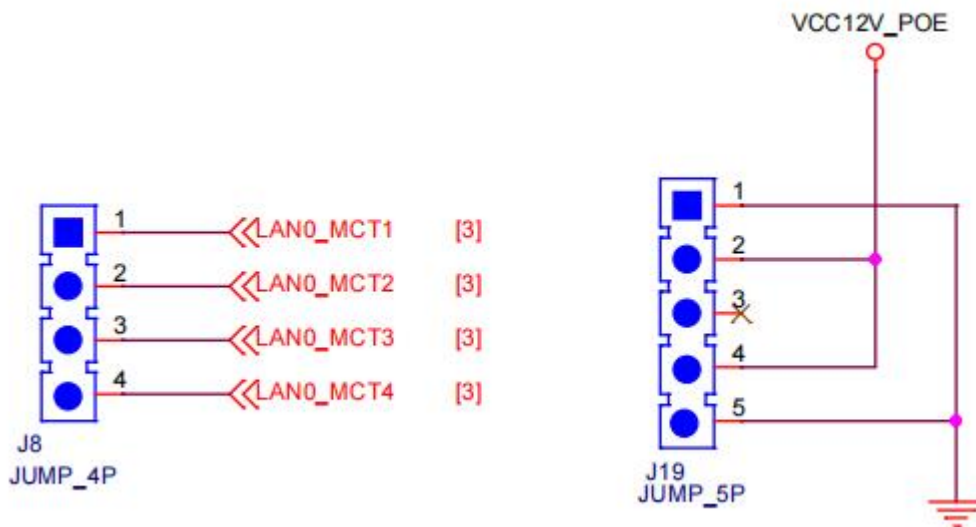
6.21 PoE PD Input Interface(J8)



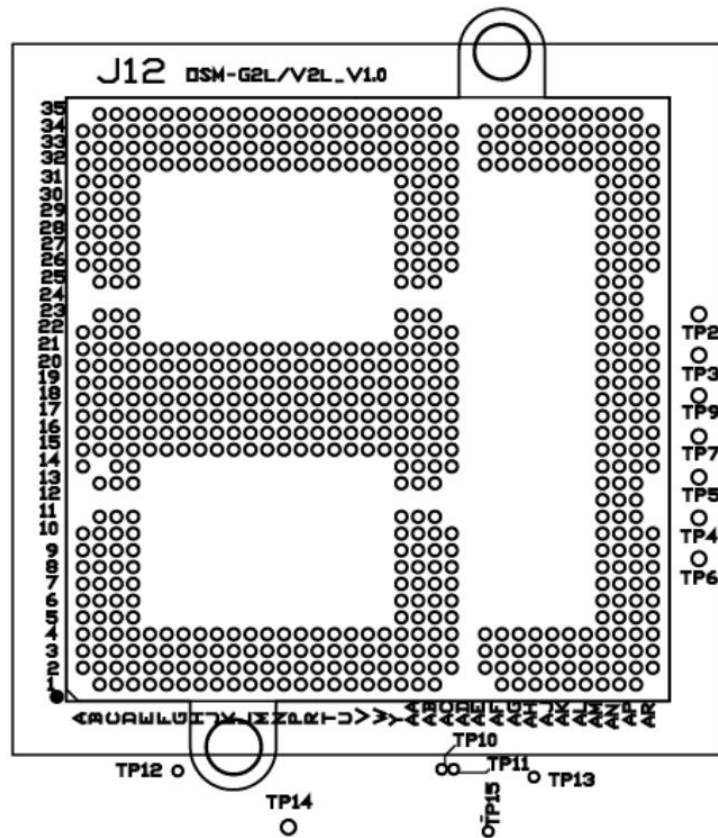
PoE PD Input interface schematic

6.21.1 Pin Definitions

Label	Pin	Functional Description	Signal description	Remark
J8	1	PoE Input 1	LAN0_MCT1	
	2	PoE Input 2	LAN0_MCT2	
	3	PoE Input 3	LAN0_MCT3	
	4	PoE Input 4	LAN0_MCT4	



6.22 Core Board Module Interface (J12)



Core board module interface schematic

Refer to the OSM-G2L Core Board specification for pin definition.

7 Statements

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